



(86) Date de dépôt PCT/PCT Filing Date: 2012/08/03
(87) Date publication PCT/PCT Publication Date: 2013/02/14
(85) Entrée phase nationale/National Entry: 2014/02/06
(86) N° demande PCT/PCT Application No.: US 2012/049488
(87) N° publication PCT/PCT Publication No.: 2013/022742
(30) Priorité/Priority: 2011/08/11 (US13/207,522)

(51) Cl.Int./Int.Cl. *A61F 13/42* (2006.01),
G01V 15/00 (2006.01), *G08B 21/20* (2006.01)
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(54) Titre : CAPTEURS D'HUMIDITE
(54) Title: WETNESS SENSORS

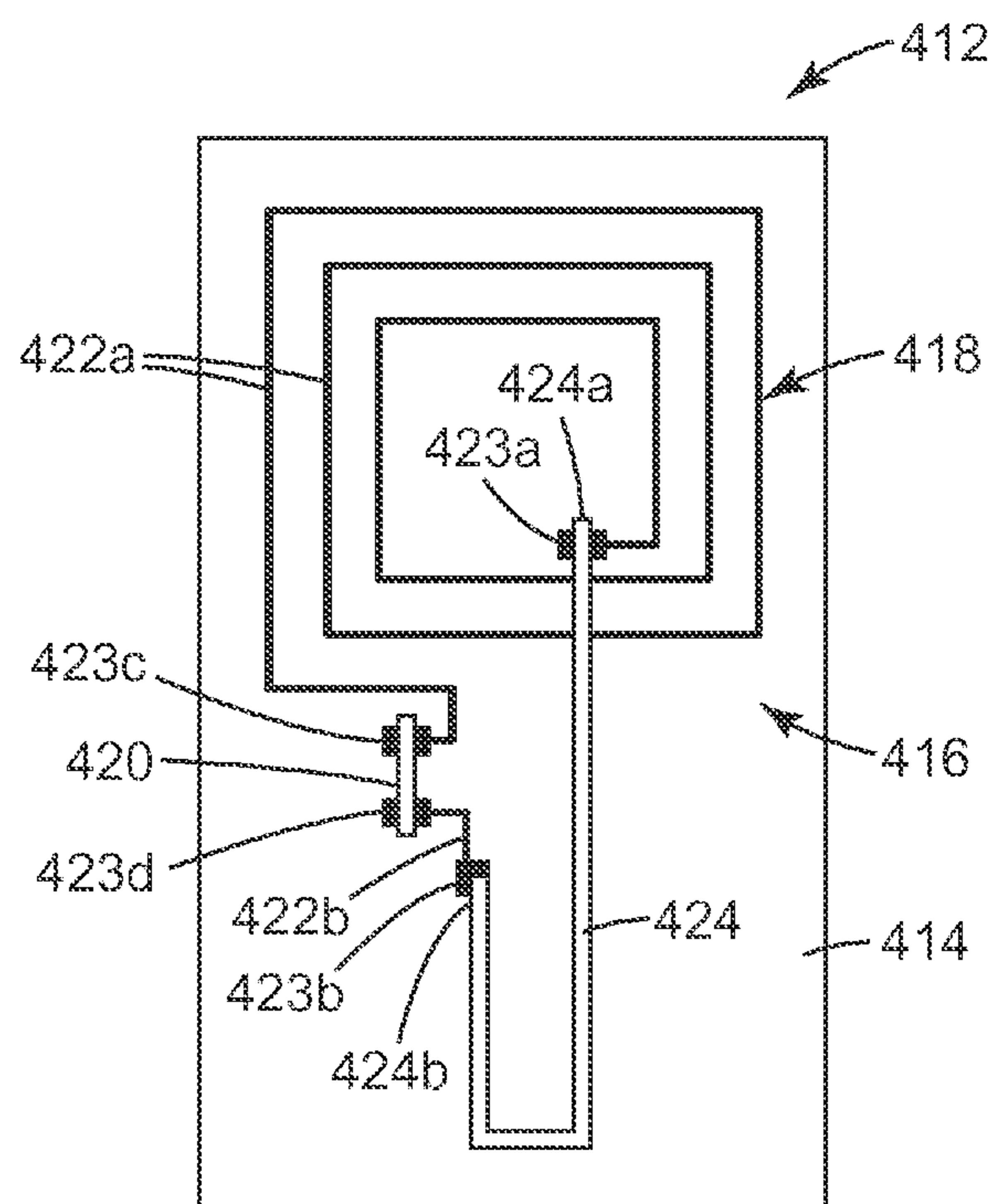


Fig. 4

(57) Abrégé/Abstract:

A wetness sensor includes a self-supporting substrate and an electrically conductive trace carried by the substrate. The trace is patterned to provide at least a portion of a tuned RF circuit, which may be disposed on only one side of the substrate and

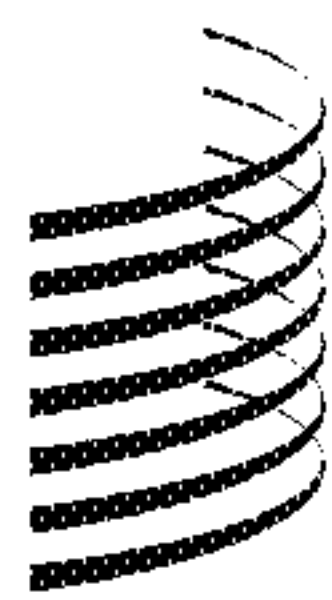


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(57) **Abrégé(suite)/Abstract(continued)**:

characterized by an impedance or resistance. The trace is not self-supporting. The substrate is adapted to dissolve, swell, or otherwise degrade when contacted by a target fluid. Such degradation produces a drastic change in the operation of the RF circuit, which can be interpreted by a remote reader as a "wet" condition. Contact of the substrate by the target fluid may change the impedance or resistance of the RF circuit by at least a factor of 5, 10, 100, or 1000, and/or may cause the trace to disintegrate so as to provide the RF circuit with an open circuit, and/or may substantially render the RF circuit inoperative.

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau

WIPO | PCT

(10) International Publication Number
WO 2013/022742 A1(43) International Publication Date
14 February 2013 (14.02.2013)

(51) International Patent Classification:

A61F 13/42 (2006.01) *G01V 15/00* (2006.01)
G08B 21/20 (2006.01)

(21) International Application Number:

PCT/US2012/049488

(22) International Filing Date:

3 August 2012 (03.08.2012)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

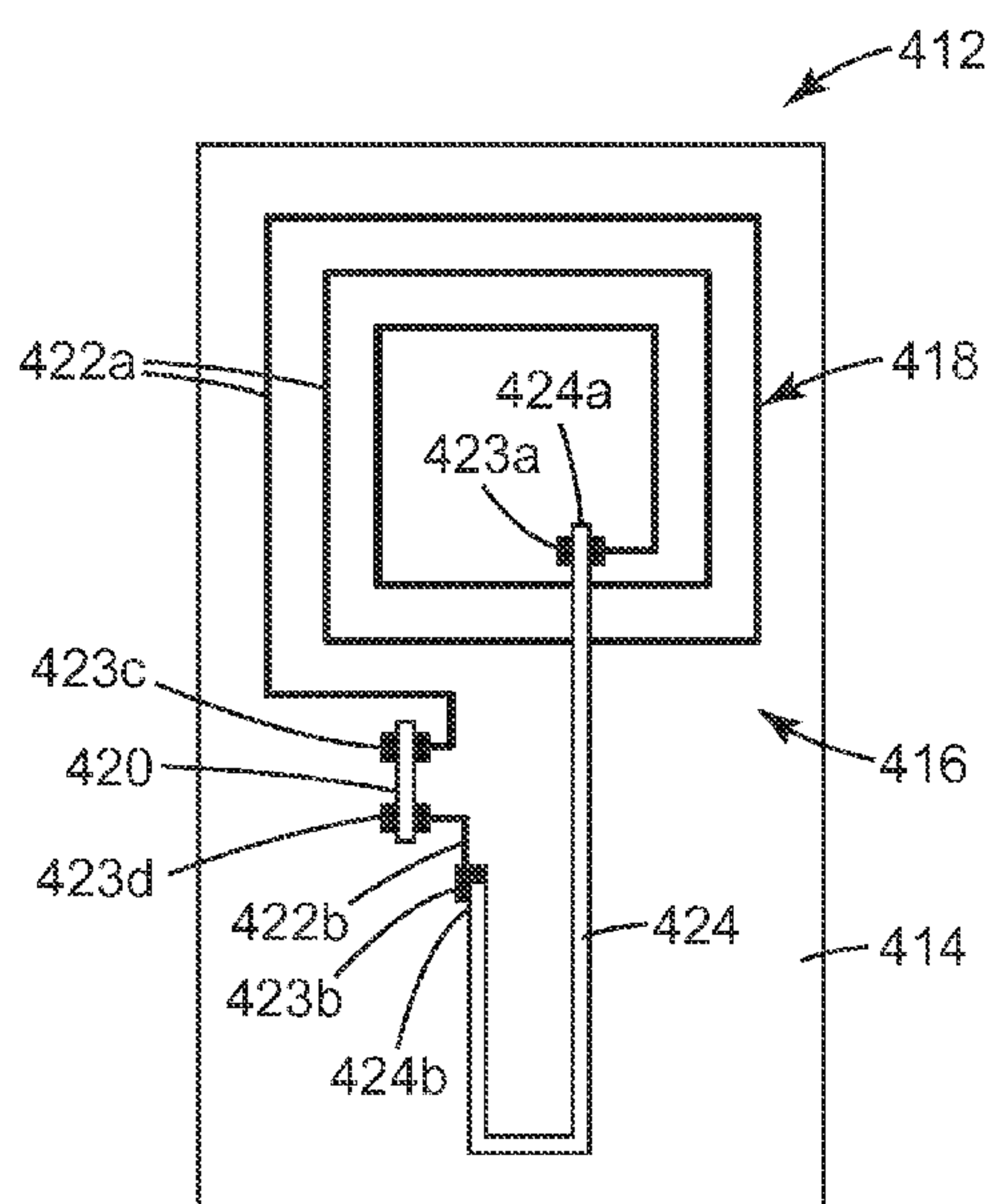
13/207,522 11 August 2011 (11.08.2011) US

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(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM,

[Continued on next page]

(54) Title: WETNESS SENSORS

**Fig. 4**

(57) Abstract: A wetness sensor includes a self-supporting substrate and an electrically conductive trace carried by the substrate. The trace is patterned to provide at least a portion of a tuned RF circuit, which may be disposed on only one side of the substrate and characterized by an impedance or resistance. The trace is not self-supporting. The substrate is adapted to dissolve, swell, or otherwise degrade when contacted by a target fluid. Such degradation produces a drastic change in the operation of the RF circuit, which can be interpreted by a remote reader as a "wet" condition. Contact of the substrate by the target fluid may change the impedance or resistance of the RF circuit by at least a factor of 5, 10, 100, or 1000, and/or may cause the trace to disintegrate so as to provide the RF circuit with an open circuit, and/or may substantially render the RF circuit inoperative.

WO 2013/022742 A1

TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

- (84) Designated States** (*unless otherwise indicated, for every kind of regional protection available*): ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Declarations under Rule 4.17:

- *as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii))*
- *as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii))*

Published:

- *with international search report (Art. 21(3))*
- *before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments (Rule 48.2(h))*

WETNESS SENSORS

5 FIELD OF THE INVENTION

This invention relates generally to wetness sensors, as well as articles and systems that incorporate such sensors, and methods pertaining to such sensors.

BACKGROUND

10 Millions of young and old wear diapers every day. For both of these groups, checking for wetness may require relying on others. In the case of adult patients who are wearing a diaper due to a medical condition or life situation, an unnoticed wet diaper can become a health risk to the occupant in some circumstances. Diaper rash and skin ulcers are just two possible medical conditions that may result from prolonged exposure to wetness. For both the health risk to the patient and the possible monetary
15 liability for the health care provider, processes and procedures for enhanced diaper monitoring are desirable.

In some places, standard monitoring procedures for adult patients requiring the use of a diaper is to monitor the patient for incontinence at least once every four hours. If the patient is unable to communicate the state of the diaper on their own, a physical check of the diaper is required by the
20 caregiver. Physically turning the patient is commonly required in order to make a satisfactory physical check. This can pose a health risk to the nurse or work staff, and, for heavier patients, additional personnel or even a mechanical lifting device may be required. Eliminating this time consuming and undignified procedure, by interrogating the state of the diaper without performing a physical check, would be highly desirable.

25 Others have proposed wetness sensors for use in diapers. See, for example, U.S. Patent Application Publication US 2008/0300559 (Gustafson et al.). See also U.S. Patent Application Publications US 2004/0064114 (David et al.), US 2004/0070510 (Zhang et al.), US 2005/0156744 (Pires), US 2006/0058745 (Pires), US 2007/0083174 (Ales, III et al.), US 2008/0132859 (Pires), and US 2008/0266123 (Ales et al.), and U.S. Patents 6,373,395 (Kimsey), 6,583,722 (Jeutter et al.), 6,603,403
30 (Jeutter et al.), and 6,774,800 (Friedman et al.). Nevertheless, the widespread use of wetness sensors in diapers -- and other applications -- has yet to be realized.

BRIEF SUMMARY

We have developed a family of sensors that can detect wetness and that can be remotely
35 interrogated. These sensors are also compatible with low cost manufacturing techniques. We have found that the sensors can be adapted not only for use in diapers or other absorbent garments, but also in other end use applications in which it is desirable to detect wetness but difficult to visually or otherwise directly observe the wetness. Such other applications may involve incorporating the wetness sensors in construction-related articles such as wall board, insulation, flooring, roofing, and fittings and support

WO 2013/022742

PCT/US2012/049488

structures to detect leakage from pipes underground, beneath floors, behind walls, or above ceilings, for example. Other applications may involve incorporating the wetness sensors in packages or boxes to detect leakage or thawing, e.g. for medical or automotive applications, for example.

We describe herein, among other things, sensors that include a self-supporting substrate and an electrically conductive trace carried by the substrate. The conductive trace is patterned to provide at least a portion of a tuned RF circuit, the RF circuit preferably being disposed on only one side of the substrate and characterized by an impedance or resistance. In contrast to the substrate, the electrically conductive trace is not self-supporting. The substrate is adapted to dissolve, swell, or otherwise degrade when contacted by a target fluid. Such degradation of the substrate produces a drastic change in the operation of the RF circuit, which can be interpreted by a remote reader or interrogation device as a “wet” condition. The contact by the target fluid may change the impedance or resistance of the RF circuit by at least a factor of 5, 10, 100, or 1000. The contact by the target fluid may cause the electrically conductive trace to disintegrate so as to provide the RF circuit with an open circuit. The contact by the target fluid may substantially render the RF circuit inoperative.

The sensor may include a skin-compatible adhesive disposed on an outer surface of the sensor. Such an adhesive may comprise silicone.

In some cases, the substrate dissolves when contacted by the target fluid. In some cases, the substrate swells when contacted by the target fluid. In some cases, the substrate is or includes a flexible film having a smooth or profiled major surface. In some cases, the substrate is or includes polyvinyl alcohol (PVA). In some cases, the target fluid comprises a polar liquid, such as water, or one or more aqueous human body fluids.

In some cases, the electrically conductive trace comprises silver. In some cases, the electrically conductive trace has a thickness of less than 1 micron, or less than 100 nanometers. In some cases, the electrically conductive trace includes a coil, and the RF circuit includes at least one capacitor that is coupled to the coil to provide a resonant frequency. The electrically conductive trace is preferably in intimate contact with the substrate. In some cases, the electrically conductive trace has a variable thickness and/or variable width. In some cases, the electrically conductive trace has a variable thickness, the thickness variation being associated with a structured interface between the conductive trace and the substrate. In some cases, the RF circuit also includes an electrically conductive linking member, such as a jumper, that connects two portions of the electrically conductive trace.

Absorbent garments such as diapers, as well as other articles, that incorporate the disclosed wetness sensors are also disclosed. In the case of an absorbent garment, the garment may include a liquid-permeable sheet, a liquid-impermeable sheet, and an absorbent material trapped between the liquid-permeable sheet and the liquid-impermeable sheet. The wetness sensor may be disposed between the liquid-permeable sheet and the liquid-impermeable sheet, or between the liquid-permeable sheet and a user's body. Preferably, the wetness sensor is disposed between the liquid-impermeable sheet and the absorbent core so that it will degrade when the core is saturated and will not be triggered by the release of only a small amount of target fluid.

Articles used in building construction that incorporate the disclosed wetness sensors are also disclosed. Such construction articles may be or include wall board, insulation, flooring (including without limitation carpeting), roofing, and/or fitting(s) or support structure(s) for pipe(s).

We describe systems in which at least one of the disclosed wetness sensors is combined with a reader configured to remotely assess a condition of the tuned RF circuit so as to assess the condition of the sensor. The reader may be configured for mounting in or on a mobile or stationary support for a person, e.g., a bed, chair (including e.g. a wheel-chair or rocking chair), cart, or other mobile or stationary support.

Related methods, systems, and articles are also discussed.

These and other aspects of the present application will be apparent from the detailed description below. In no event, however, should the above summaries be construed as limitations on the claimed subject matter, which subject matter is defined solely by the attached claims, as may be amended during prosecution.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 is a schematic perspective view of a rolled-up sheet or web containing a large number of wetness sensors before slitting or otherwise converting the sheet into individual sensor tags;

FIGS. 2a and 2b are schematic circuit diagrams of exemplary wetness sensors;

FIG. 2c is a schematic block diagram of an exemplary remote interrogation device or reader;

FIG. 3a is a schematic diagram of a detection system including a wetness sensor and a reader, where the wetness sensor is in a “dry” state;

FIG. 3b is a schematic diagram similar to that of FIG. 3a, but where the wetness sensor is in a “wet” state;

FIGS. 4, 5, 6, and 7 are schematic plan views of exemplary wetness sensors;

FIG. 8 is a schematic perspective view of a detail of an exemplary wetness sensor;

FIG. 9a is a schematic side or cross-sectional view of a portion of a wetness sensor;

FIG. 9b is a schematic side or cross-sectional view of a portion of another wetness sensor;

FIGS. 10a and 10b are schematic side or cross-sectional views of sensor substrates for use in wetness sensors, the substrates each having a conductive trace of variable thickness;

FIG. 10c is a schematic plan view of a sensor substrate for use in wetness sensors, the substrate having a conductive trace of variable width;

FIG. 11 is a plan view of a sheet or web on which is printed circuit elements for use in wetness sensors;

FIG. 12 is a photograph of a sheet of PVA on which has been printed a conductive trace patterned to provide a portion of a tuned RF circuit;

FIG. 12a is a U-shaped component suitable for use in the disclosed wetness sensors;

FIG. 13 is a schematic diagram showing different end-use applications of the wetness sensor; and

FIG. 14a is a schematic plan view of a diaper or similar incontinence garment, and FIG. 14b is a schematic cross-sectional view taken along lines 14b-14b in FIG. 14a.

In the figures, like reference numerals designate like elements.

5 DETAILED DESCRIPTION OF ILLUSTRATIVE EMBODIMENTS

In FIG. 1, we see a rolled-up sheet or web **110** which may be fabricated using high volume film handling equipment. The web **110** includes a flexible substrate **114** to which an electrically conductive trace has been applied, the trace forming at least a portion of a tuned RF circuit **116**. The trace typically forms at least an inductive coil, but it may also include other distinct circuit elements and connection
10 features, as exemplified more fully below. The conductive trace, as well as the remainder of the RF circuit, is thus carried by the substrate **114**.

Although only one circuit **116** is shown in the figure, the reader will understand that substantially the same or similar tuned RF circuits are preferably provided in an array on the web, one such circuit being disposed in each region labeled **112**, and all such circuits preferably being disposed on the same
15 side of the web **110**. The reference number **112** may thus refer to individual sensors in the form of tags or labels that may be obtained by converting web **110** by slitting or cutting operations along lines **113a**, **113b**, for example.

The tuned RF circuit **116** typically includes one or more discrete circuit elements in addition to the electrically conductive trace. For example, the circuit **116** may include a separate jumper (an
20 electrically conductive linking member) and a capacitor, as discussed further below, that are carried by the substrate **114** and connected to the conductive trace so as to complete the RF circuit **116** and provide the desired functionality. In some cases, the conductive trace may itself include one or more capacitors, in addition to an inductive coil. If desired, any discrete circuit elements that form part of the RF circuit **116** may be attached to the substrate **114**, or to a portion of the RF circuit **116**, after slitting or cutting the
25 web into individual sensor tags **112**, rather than before such slitting or cutting. Alternatively, one or more discrete circuit elements may be attached to the substrate **114**, or to a portion of the RF circuit **116**, while the web **110** is still intact, before subdividing the web into the individual tags. The conductive trace and other component(s) of the RF circuit **116** are preferably carried by the substrate and disposed on only one side of the substrate **114**. Such an arrangement is advantageous from a manufacturing standpoint so that
30 only one-sided film processing can be employed.

The substrate **114** is not only flexible, but it is also self-supporting. In this regard, a substrate is said to be self-supporting if it has a mechanical integrity sufficient to permit handling of the substrate without undue breakage, tears, or other damage that would make it unsuitable for its intended application.

Significantly, the substrate is adapted to dissolve, swell, or otherwise degrade when contacted by
35 a target fluid such as water, and the electrically conductive trace is not self-supporting. With this combination of features, exposure of the sensor tag to the target fluid can produce a drastic change in the physical structure of the RF circuit, and a corresponding drastic change in the operation of the RF circuit, the latter of which can be interpreted by a remote reader or interrogation device as a “wet” condition. For

example, in cases where the substrate is tailored to dissolve completely or even partially when contacted by the target fluid, the conductive trace and other RF circuit elements may simply collapse, crumble, or fall apart in the absence of the structural support that was originally provided by the substrate.

The drastic change in operation of the RF circuit may be manifested by a change in resistance or impedance of the circuit by at least a factor of 5, 10, 100, or 1000, for example. In this regard, a “change in resistance or impedance” refers to a change in the magnitude of the resistance or impedance.

Impedance extends the concept of direct current (DC) resistance to alternating current (AC) circuits, describing not only the relative amplitudes of the voltage and current, but also the relative phases.

Impedance describes a measure of opposition to alternating current and is described by a complex

number. The real part of impedance describes the resistance (amplitude ratio of voltage and current), and the imaginary part describes the phase differences. Phase differences only occur when the circuit has a capacitive or inductive component, and typically a plus sign is used to indicate the inductance of the imaginary part and a negative sign is used to indicate the capacitance of the imaginary part. An impedance analyzer works by measuring the ratio of voltage to current through the electronic circuit.

Alternately or in addition, the drastic change in operation of the RF circuit may be manifested by a change in resonant frequency, Q-factor, bandwidth, amplitude, and/or other resonant characteristic.

Alternatively or in addition, the drastic change in operation may be manifested by a substantial disintegration or break-up of the electrically conductive trace so as to provide the RF circuit with an open circuit. Alternatively or in addition, the drastic change in operation may be manifested by the RF circuit being rendered substantially inoperative.

Exemplary tuned RF circuits suitable for use in the disclosed wetness sensors are shown schematically in FIGS. 2a and 2b. In FIG. 2a, a simple RF circuit **216** comprises an inductor **218** and a capacitor **220** connected as shown. The inductance L and capacitance C of these components combine to provide the LC circuit **216**, the circuit having a resonant frequency f (expressed in units of cycles per second, or Hertz) given by:

$$f = \frac{1}{2\pi\sqrt{LC}}.$$

The values of L and C are preferably selected so that the resonant frequency is tuned to a desired portion of the radio frequency (RF) electromagnetic spectrum, e.g., a desired portion of the spectrum from 30 kHz to 300GHz. In preferred embodiments the resonant frequency may be in a desired portion of the narrower range from 1 to 100 MHz, or more specifically at a target frequency of 13.56 MHz, for example. In any case, the tuned RF frequency of the sensor circuit is preferably selected to be compatible with (e.g. to substantially match, overlap with, or fall within) a frequency range of a remote reader or interrogation device, the reader and the RF circuit of the sensor thus operating as a wetness detection system. The inductor **218** acts as an antenna to receive RF electromagnetic energy from the reader if the energy is close to the resonant frequency of the circuit, and the inductor **218** then re-emits at least some of the absorbed energy at or near the circuit's resonant frequency.

The RF circuit **216b** of FIG. 2b is similar to circuit **216**, except that the single capacitor **220** has been replaced with two separate capacitors **220a**, **220b** connected in series. In alternative embodiments, more than two separate capacitors may be used, and they all may be connected in series or they may be connected in other ways. Furthermore, although only one inductor coil is preferred in the disclosed RF circuits, embodiments having more than one inductor are also contemplated. In some embodiments, the various elements of the RF circuit are connected to each other in such a way as to provide an RF circuit whose response can be approximated by the simple LC resonant circuit of FIG. 2a. For example, the individual capacitors **220a**, **220b** of FIG. 2b can be mathematically represented by a single capacitor **220** having an appropriate capacitance C. The values of the various circuit elements making up the RF circuit (e.g. the inductance of inductor **218**, and the capacitances of capacitors **220a**, **220b**) are again selected to provide a resonant frequency tuned to a desired portion of the RF spectrum, as discussed above. Virtually all real circuits contain some amount of resistance. In some embodiments of the disclosed wetness sensors, the RF circuit may have a resistance that is negligible, while in other cases the RF circuit may have a non-negligible resistance. In the latter cases, the RF circuit may include one or more individual resistors, e.g., to form an RLC resonant circuit.

In some cases, additional circuitry (not shown) may be included in the tuned RF circuit for emitting an identification code via the antenna. Such additional circuitry can be the same as or similar to circuitry used in known radio frequency identification (RFID) devices. Devices that are capable of transmitting a code to the reader are typically referred to as RFID devices. Devices not capable of transmitting an identification code are sometimes referred to as electronic article surveillance (EAS) devices. EAS devices absorb and disrupt an electromagnetic field, such as an RF field, emitted by a reader. The disruption of the field may be detected by the reader and interpreted to indicate the presence of an EAS device. The tuned RF circuits used in the disclosed wetness sensors are preferably of the generally simpler EAS design, although other designs are contemplated, including but not limited to the more complex RFID design. Preferred tuned RF circuits are passive in nature, i.e., they do not incorporate a battery or other on-board source of power, but instead derive power from coupling to the electromagnetic field emitted by the reader antenna. In some cases, however, depending on the end-use application of the wetness sensor, the tuned RF circuit may be active in nature, i.e., it may include a battery or other power source. In any case, the tuned RF circuit is typically characterized by a resonant frequency and a circuit impedance.

FIG. 2c is a schematic block diagram of an exemplary remote interrogation device or reader **230**. The reader **230** includes an inductor **232**, an RF source **234**, and a resonance analyzer **236**. Energy is stored in the fields surrounding the inductor **232**, which serves as an antenna. This stored energy may be coupled to the tuned RF circuit of a wetness sensor if the wetness sensor is in the vicinity of the reader **230**. The resonance analyzer **236** may be configured to detect changes in the amount of energy coupled from the antenna of the reader **230** to the tuned RF circuit, such coupling occurring if the resonant frequency of the tuned RF circuit is sufficiently near the resonant frequency of the reader circuit.

Perturbations in the interrogator signal that are attributable to changes in the energy coupled by the tuned RF circuit can be considered to constitute a sensing signal or sensing circuit signal.

FIGS. 3a and 3b are schematic diagrams of a detection system including a wetness sensor and a reader **330**. In FIG. 3a, the wetness sensor **312a** is in a “dry” state, and in FIG. 3b the wetness sensor has
5 been contacted by water or another target fluid to produce the wetness sensor **312b** in a “wet” state.

In FIG. 3a, the reader **330** broadcasts an RF signal, at least a portion of which has a suitable frequency component that can be absorbed by the tuned RF circuit **316a** of the sensor **312a**. The sensor **312a** converts some of the absorbed energy to a (weaker) sensing signal, which is broadcast by the circuit **316a** and sensed by the reader **330**. The reader **330** interprets the sensing signal from the circuit **316a** as a
10 “dry” condition, and an indicator light or other suitable status output may be provided by the reader **330**.

In FIG. 3b, the reader **330** again broadcasts the same RF signal. The sensor **312b** is in the vicinity of the reader just as sensor **312a** was, but exposure of the sensor to the target fluid has caused the substrate that carries the tuned RF circuit to partially or completely dissolve (or to swell or otherwise degrade). For this reason the substrate of sensor **312b** is drawn in broken lines. A tuned RF circuit **316b**
15 is shown in the figure, but the circuit may be wholly or partially inoperative as a result of the absence or degradation of the supporting substrate. Alternatively, the circuit may remain operative, but it may have very different characteristics from those of circuit **316a**, e.g., very different impedance, very different resonant frequency, Q-factor, bandwidth, amplitude, and/or other resonant characteristic. Consequently, the sensor **312b** may provide no sensing signal, or it may provide a sensing signal that is drastically
20 different from the sensing signal provided by the sensor **312a** before contact with the target fluid. The reader **330** interprets the absence of a sensing signal, or the drastically different sensing signal, as a “wet” condition. A “wet” indicator light or other suitable status output may then be provided by the reader **330**.

FIG. 4 provides a schematic view of one exemplary wetness sensor **412**. The sensor **412** comprises a self-supporting substrate **414** and a tuned RF circuit **416** carried by the substrate. The
25 substrate **414** may be a relatively small sample that has been cut from a larger piece of the same substrate material, e.g. in a converting operation on a continuous web of substrate material. Preferably, the substrate **414** is thin enough to be flexible, but thick enough to be self-supporting. As already mentioned, the substrate is preferably composed of a material that dissolves, swells, or otherwise degrades when contacted by a target fluid. Preferred substrate materials are also melt-extrudable or solvent cast and are
30 capable of being cast into flexible films. For aqueous sensors, suitable materials may be selected from any of the known natural or synthetic water-soluble or water-dispersible materials. An exemplary film-forming polymer or oligomer substrate material is polyvinyl alcohol (PVA). PVA is a polar material, and it substantially dissolves and/or swells when exposed to water or other polar liquids, including aqueous human body fluids such as urine or blood. Polymers of PVAs may be prepared from polyvinyl acetate
35 and can be commercially obtained in a variety of molecular weights and hydrolysis levels. Alternative substrate materials include, but are not limited to: frangible papers such as tissue paper or newsprint; vegetable natural polymers such as alginic acid and alginic acid derivated polymers, arabinogalactan, cellulose derivatives including but not limited to hydroxyethylcellulose, hydroxypropylcellulose,

WO 2013/022742

PCT/US2012/049488

hydroxylpropyl methylcellulose, methylcellulose, carboxymethylcellulose, starch, and starch derivatives; microorganism-derived natural polymers such as polysaccharides, polymers derived from animals including gelatin, collagen, mucopolysaccharides and the like; polyoxyalkylenes; polymers and copolymers derived from ethenically unsaturated monomers including, but not limited to vinylic monomers, acrylates and methacrylates, acrylamides and methacrylamides, and the like; polyethylenemines; polylactic acid; polyglycolic acid; and mixtures including one or more of the foregoing. Additional suitable substrate materials include polyethylene oxide or polyethylene glycol, pectin, pullulan, and carbopol-based polymer films. Still other suitable substrate materials may be selected from the materials disclosed in PCT publication WO 02/092049 (Godbey et al.), “System for Delivering Cosmetics and Pharmaceuticals”, incorporated herein by reference. As disclosed in that document, plasticizers can be used to reduce the brittleness of the film, thereby making the film tougher, more conformable, and generally improving its handling properties. Another suitable substrate material is Water-Soluble Wave Solder Tape #5414 available from 3M Company, which is a tape having a PVA film backing, a synthetic water soluble adhesive, and a Kraft paper liner.

In some cases, the wetness sensor may be designed to detect a target fluid other than water, or may even detect a fluid other than a polar liquid, e.g., a non-polar liquid derived from petroleum-based products such as gasoline, kerosene, hexane, heptane, toluene, and other aromatic, straight chained, or branched hydrocarbons or mixtures thereof. For a wetness sensor designed to detect a non-polar liquid, the substrate is preferably composed of a non-polar material. For example, polystyrene is a non-polar material that may be used as, or included in, a substrate and will dissolve, swell, or otherwise degrade when contacted by a non-polar target fluid. Other exemplary substrates that will degrade with non-polar target fluids include those made from ABS, EPDM, PVC, polypropylene, and other non-polar materials that preferably have little or no crosslinking, plasticizers or stabilizers.

The sensor substrate **414** may be a unitary film, i.e., it may have a uniform composition throughout the entire space or volume of the substrate. Alternatively, the substrate may have a non-uniform composition. One type of a non-uniform composition is a stacked layered medium, or a striped medium with side-by-side lanes of differing materials, at least one of which is degradable by the target fluid. For example, the substrate may be composed of two distinct layers of different materials, or three or more layers of materials that may all be different from each other, or that may include materials in an alternating sequence, for example. Blended materials, e.g., composed of a first material providing a continuous phase and a second material providing a dispersed phase, are also contemplated. In cases where the sensor substrate is composed of a plurality of distinct materials, whether layered, blended, coextruded, striped, or otherwise, one, some, or all of the plurality of materials may be soluble, or may swell, or may otherwise degrade, for example, in the presence of the target fluid.

The wetness sensor **412** also includes an electrically conductive trace that has been applied to the substrate **414**. In the embodiment of FIG. 4, the conductive trace is divided into two sections: trace **422a**, and trace **422b**. These sections are referred to collectively as conductive trace **422**. The trace **422** includes a spiral-shaped path that forms an inductive coil **418**. The trace **422** also includes widened areas

or contact pads labeled **423a**, **423b**, **423c**, and **423d**. The pad **423a** provides an inner terminus of the trace **422** on an interior of the coil **418**, and pad **423b** provides an outer terminus of the trace **422** on an exterior of the coil **418**.

Trace **422** may be applied directly to the exposed major surface of the substrate **414**, or one or more intervening layers, e.g. to promote adhesion, may be included. The trace **422** may be formed on the substrate by any suitable technique, including printing, coating, etching, electrodeposition, vapor deposition, thermographic transfer, and/or other known patterning techniques. The trace **422** may be composed of a metal or other suitable electrically conductive materials, such as graphite and/or one or more conductive polymers, for example. Exemplary conductive materials include copper, silver, and/or nickel, but this list should not be construed as limiting. The trace **422** preferably has a thickness that is substantially less than that of the substrate **414**. In some embodiments, the trace **422** has a thickness that is less than 1 micron, or less than 100 nanometers, for example. Preferably, the trace **422** is so mechanically delicate that it is unable to maintain its physical integrity in the absence of a supporting substrate, i.e., substrate **414**. Trace **422**, when considered by itself (separately from the supporting substrate **414**), is thus not self-supporting as that term is used above. Consequently, if some or all of the substrate **414** dissolves in the presence of the target fluid, the trace **422** loses its mechanical integrity and gives rise to a drastic change in the operation of the RF circuit **416**.

The circuit **416** also includes a separate, discrete capacitor **420**, which is connected between pads **423c** and **423d** of trace **422**. The capacitor **420** may be a chip capacitor or any other suitable capacitor component capable of being attached to the pads **423c**, **423d** as shown. Attachment may be accomplished by soldering, adhesives, or by any other suitable technique.

Finally, the circuit **416** also includes a jumper **424**. The jumper **424** may provide a low impedance conductive path between inner pad **423a** and outer pad **423b**, with little or no resistance, capacitance, or inductance of its own. A first terminus **424a** of the jumper **424** makes direct electrical contact with pad **423a**, and a second terminus **424b** of the jumper **424** makes direct electrical contact with pad **423b**, while the jumper **424** avoids making any electrical contact with portions of the trace **422** that it crosses over. (In FIG. 4, jumper **424** crosses over two of the loops in the coil **418** but does not make electrical contact with those loops.) In this manner, the jumper **424** has the effect of connecting the coil **418** and the capacitor **420** substantially as shown in the schematic circuit diagram of FIG. 2a. The jumper may be constructed of any suitable conductive material(s) and optional insulating material(s) that allows the jumper to provide a conductive path between pads **423a** and **423b**, while remaining insulated from portions of the coil **418** that it crosses over. An exemplary jumper **424** is or comprises a metal or other conductive layer disposed on an insulating polymer substrate, but other constructions are also possible. Insulating and/or conducting adhesives can also be printed on the substrate **414** or jumper **424**, or otherwise be applied selectively between the jumper **424** on one side, and the substrate **414** and trace **422** on the other side, so that the jumper **424** is held securely in place to the substrate **414** while making the necessary electrical connections and avoiding other electrical connections. Additional information on suitable jumpers is provided further below.

The discrete circuit elements of the capacitor **420** and the jumper **424** may be attached to the substrate **414**, and to the conductive trace **422**, while a web of substrate material is still intact, or after such web is slit or cut to provide the individual sensor tag **412**, or a combination thereof (wherein one discrete circuit element is attached to the substrate before converting, and the other discrete circuit element is attached after converting). The discrete circuit elements (e.g., elements **420**, **424**) are preferably carried by the substrate and disposed on a same side of the substrate **414** as conductive trace **422**.

In an alternative embodiment, the sensor **412** may include one or two additional capacitors connected in series with the discrete capacitor **420**, the additional capacitor(s) being formed at the junction of jumper terminus **424a** and pad **423a**, and/or at the junction of jumper terminus **424b** and pad **423b**. This can be accomplished by avoiding a direct electrical connection between the conductor at jumper terminus **424a** and the contact pad **423a**, and/or between the conductor at jumper terminus **424b** and the contact pad **423b**, and by instead including an insulating material (such as an insulating adhesive or film) between the appropriate jumper terminus and corresponding contact pad of the conductive trace. By controlling the thickness of the insulating material, the size of the conductor at the jumper terminus, the size of the contact pad, and the relative position of the jumper terminus and the contact pad, a desired capacitance can be achieved at the selected junction(s).

Turning now to FIG. 5, we see there a schematic view of another wetness sensor **512**. Like sensor **412**, the sensor **512** includes a self-supporting substrate **514** and a tuned RF circuit **516** carried by the substrate. Features of the substrate **414** discussed above are also applicable to the substrate **514**. For example, the substrate **514** is preferably thin enough to be flexible, but thick enough to be self-supporting. Substrate **514** also comprises a material that dissolves, swells, or otherwise degrades when contacted by a target fluid. Substrate **514** may be a unitary film, or it may have a non-uniform composition as discussed elsewhere herein.

The wetness sensor **512** also includes an electrically conductive trace that has been applied to the substrate **514**. Similar to the embodiment of FIG. 4, the conductive trace is divided into two sections: trace **522a**, and trace **522b**. These sections are referred to collectively as conductive trace **522**. The trace **522** includes a spiral-shaped path that forms an inductive coil **518**. The trace **522** also includes widened areas or contact pads labeled **523a**, **523b**. The pad **523a** provides an inner terminus of the trace **522** on an interior of the coil **518**, and pad **523b** provides an outer terminus of the trace **522** on an exterior of the coil **518**.

Instead of the discrete capacitor **420** of FIG. 4, the sensor **512** includes an integrated capacitor **520** which may be formed by interdigitated portions of trace **522a** and trace **522b**. The geometry of the interdigitated portions, such as the number of individual tines or prongs and their respective lengths and spacing, can be tailored to provide a desired amount of capacitance. Providing an integrated capacitor is advantageous by avoiding the manufacturing steps required to attach a discrete capacitor, and avoiding reliability and yield issues associated with a discrete capacitor, such as attachment failure, misalignment, detachment, and so forth.

Notwithstanding the clear design differences between trace **522** and trace **422**, other design features discussed in connection with trace **422** are also applicable to trace **522**. For example, the trace **522** may be formed on the substrate **524** by any suitable technique, including printing, coating, etching, electrodeposition, vapor deposition, thermographic transfer, and/or other known patterning techniques.

Further, the trace **522** may be composed of any suitable electrically conductive materials, and may have a thickness that is substantially less than that of the substrate **514**, the thickness of the trace **522** being in some embodiments less than 1 micron, or less than 100 nanometers, for example. The trace **522** when considered by itself is not self-supporting. Consequently, if some or all of the substrate **514** dissolves in the presence of the target fluid, the trace **522** loses its mechanical integrity and gives rise to a drastic change in the operation of the RF circuit **516**.

Similar to circuit **416**, the circuit **516** also includes a jumper **524**. In one embodiment, the jumper **524** provides a low impedance conductive path between inner pad **523a** and outer pad **523b**, with little or no resistance, capacitance, or inductance of its own. A first terminus **524a** of the jumper **524** makes direct electrical contact with pad **523a**, and a second terminus **524b** of the jumper **524** makes direct electrical contact with pad **523b**, while the jumper **524** avoids making any electrical contact with portions of the trace **522** that it crosses over. (In FIG. 5, jumper **524** crosses over two of the loops in the coil **518** but does not make electrical contact with those loops.) In this manner, the jumper **524** has the effect of connecting the coil **518** and the capacitor **520** substantially as shown in the schematic circuit diagram of FIG. 2a. Features of the jumper **424** discussed above are also applicable to jumper **524**.

The jumper **524**, which may be the only discrete circuit element of tuned RF circuit **516**, or may be one of a variety of discrete circuit elements, may be attached to the substrate **514** and conductive trace **522** while a web of substrate material is still intact, or after such web is slit or cut to provide the individual sensor tag **512**. The discrete circuit element(s) including element **524** is or are preferably carried by the substrate and disposed on a same side of the substrate **514** as conductive trace **522**.

Similar to sensor **412**, the sensor **512** may alternatively include one or two additional capacitors connected in series with the discrete capacitor **520**, the additional capacitor(s) being formed at the junction of jumper terminus **524a** and pad **523a**, and/or at the junction of jumper terminus **524b** and pad **523b**. This can be accomplished by avoiding a direct electrical connection between the conductor at jumper terminus **524a** and the contact pad **523a**, and/or between the conductor at jumper terminus **524b** and the contact pad **523b**, and by instead including an insulating material (such as an insulating adhesive or film) between the appropriate jumper terminus and corresponding contact pad of the conductive trace. By controlling the thickness of the insulating material, the size of the conductor at the jumper terminus, the size of the contact pad, and the relative position of the jumper terminus and the contact pad, a desired capacitance can be achieved at the selected junction(s).

We see in FIG. 6 a schematic view of another wetness sensor **612**. Like sensors **412** and **512**, the sensor **612** includes a self-supporting substrate **614** and a tuned RF circuit **616** carried by the substrate. Features of the substrates **414**, **514** discussed above are also applicable to the substrate **614**. For example, the substrate **614** is preferably thin enough to be flexible, but thick enough to be self-supporting.

Substrate **614** also comprises a material that dissolves, swells, or otherwise degrades when contacted by a target fluid. Substrate **614** may be a unitary film, or it may have a non-uniform composition as discussed elsewhere herein.

The wetness sensor **612** also includes an electrically conductive trace **622** that has been applied to the substrate **614**. In the embodiment of FIG. 6, the conductive trace **622** is provided in only a single contiguous section. The trace **622** includes a spiral-shaped path that forms an inductive coil **618**. The trace **622** also includes widened areas or contact pads labeled **623a**, **623b**. The pad **623a** provides an inner terminus of the trace **622** on an interior of the coil **618**, and pad **623b** provides an outer terminus of the trace **622** on an exterior of the coil **618**.

Instead of the discrete capacitor **420** of FIG. 4, or the interdigitated capacitor **520** of FIG. 5, the sensor **612** includes capacitors **620a** and **620b** that are formed at the junctions of the pads **623a**, **623b** with terminuses of a jumper **624**. These capacitors **620a**, **620b** are described further below in connection with the jumper **624**.

Notwithstanding the clear design differences between trace **622** and the traces **422**, **522**, other design features discussed in connection with traces **422**, **522** are also applicable to trace **622**. For example, the trace **622** may be formed on the substrate **614** by any suitable technique, including printing, coating, etching, electrodeposition, vapor deposition, thermographic transfer, and/or other known patterning techniques. Further, the trace **622** may be composed of any suitable electrically conductive materials, and may have a thickness that is substantially less than that of the substrate **614**, the thickness of the trace **622** being in some embodiments less than 1 micron, or less than 100 nanometers, for example. The trace **622** when considered by itself is not self-supporting. Consequently, if some or all of the substrate **614** dissolves in the presence of the target fluid, the trace **622** loses its mechanical integrity and gives rise to a drastic change in the operation of the RF circuit **616**.

As already mentioned, circuit **616** includes jumper **624**. In one embodiment, the jumper **624** provides capacitive coupling between the contact pads **623a**, **623b** and terminuses **624a**, **624b** respectively so as to provide distinct capacitors **620a**, **620b**, the jumper **624** also providing a low impedance conductive path along the jumper between the terminuses **624a**, **624b**. Capacitive coupling between a given terminus of the jumper **624** and its corresponding contact pad of the trace **622** can be accomplished by including an insulating material (such as an insulating adhesive or film) between the jumper terminus and the contact pad. By controlling the thickness of the insulating material, the size of the conductor at the jumper terminus, the size of the contact pad, and the relative position of the jumper terminus and the contact pad, a desired capacitance **620a**, **620b** can be achieved at the respective junction. The jumper **624** avoids making any electrical contact with portions of the trace **622** that it crosses over. (In FIG. 6, jumper **624** crosses over two of the loops in the coil **618** but does not make electrical contact with those loops. Furthermore, capacitive coupling between the jumper and such portions of the trace **622** is preferably negligible in comparison to capacitors **620a**, **620b**.) In this manner, the jumper **624** has the effect of providing two capacitors connected to the coil **618** substantially as shown in the schematic

circuit diagram of FIG. 2b. Features of jumpers **424**, **524** discussed above are also applicable to jumper **624**.

The jumper **624**, which may be the only discrete circuit element of tuned RF circuit **616**, may be attached to the substrate **614** and conductive trace **622** while a web of substrate material is still intact, or
 5 after such web is slit or cut to provide the individual sensor tag **612**. The discrete circuit element **624** is preferably carried by the substrate and disposed on a same side of the substrate **614** as conductive trace **622**.

In an alternative embodiment, one of the capacitors **620a**, **620b** may be eliminated by providing a direct electrical connection between the associated terminus of the jumper **624** and its corresponding
 10 contact pad of the conductive trace **622**. For example, capacitor **620a** may be eliminated by providing a direct electrical connection between terminus **624a** of the jumper and the contact pad **623a**. Alternatively, capacitor **620b** may be eliminated by providing a direct electrical connection between terminus **624b** of the jumper and the contact pad **623b**. In either case the result is a tuned RF circuit in which the (sole) remaining capacitor is connected with an inductor as shown in the circuit diagram of
 15 FIG. 2a.

FIG. 7 depicts a wetness sensor **712** that is similar in many ways to sensor **612** of FIG. 6, but with a different aspect ratio of the coil and with a straight jumper rather than a U-shaped jumper. Like sensors **412**, **512**, and **612**, the sensor **712** includes a self-supporting substrate **714** and a tuned RF circuit **716** carried by the substrate. Features of the substrates **414**, **514**, and **614** discussed above are also applicable
 20 to the substrate **714**. For example, the substrate **714** is preferably thin enough to be flexible, but thick enough to be self-supporting. Substrate **714** also comprises a material that dissolves, swells, or otherwise degrades when contacted by a target fluid. Substrate **714** may be a unitary film, or it may have a non-uniform composition as discussed elsewhere herein.

The wetness sensor **712** also includes an electrically conductive trace **722** that has been applied to
 25 the substrate **714**. In the embodiment of FIG. 7, the conductive trace **722** is provided in only a single contiguous section. The trace **722** includes a spiral-shaped path that forms an inductive coil **718**. The trace **722** also includes widened areas or contact pads labeled **723a**, **723b**. The pad **723a** provides an inner terminus of the trace **722** on an interior of the coil **718**, and pad **723b** provides an outer terminus of the trace **722** on an exterior of the coil **718**.

Similar to sensor **612**, the sensor **712** includes capacitors **720a** and **720b** that are formed at the
 30 junctions of the pads **723a**, **723b** with terminuses of a jumper **724**. These capacitors **720a**, **720b** are described further below in connection with the jumper **724**.

Notwithstanding the clear design differences between trace **722** and the traces **422**, **522**, and **622**, other design features discussed in connection with traces **422**, **522**, and **622** are also applicable to trace
 35 **722**. For example, the trace **722** may be formed on the substrate **714** by any suitable technique, including printing, coating, etching, electrodeposition, vapor deposition, thermographic transfer, and/or other known patterning techniques. Further, the trace **722** may be composed of any suitable electrically conductive materials, and may have a thickness that is substantially less than that of the substrate **714**, the

thickness of the trace **722** being in some embodiments less than 1 micron, or less than 100 nanometers, for example. The trace **722** when considered by itself is not self-supporting. Consequently, if some or all of the substrate **714** dissolves in the presence of the target fluid, the trace **722** loses its mechanical integrity and gives rise to a drastic change in the operation of the RF circuit **716**.

5 Circuit **716** includes jumper **724**. In one embodiment, the jumper **724** provides capacitive coupling between the contact pads **723a**, **723b** and terminuses **724a**, **724b** respectively so as to provide distinct capacitors **720a**, **720b**, the jumper **724** also providing a low impedance conductive path along the jumper between the terminuses **724a**, **724b**. Capacitive coupling between a given terminus of the jumper **724** and its corresponding contact pad of the trace **722** can be accomplished by including an insulating
10 material (such as an insulating adhesive or film) between the jumper terminus and the contact pad. By controlling the thickness of the insulating material, the size of the conductor at the jumper terminus, the size of the contact pad, and the relative position of the jumper terminus and the contact pad, a desired capacitance **720a**, **720b** can be achieved at the respective junction. The jumper **724** avoids making any electrical contact with portions of the trace **722** that it crosses over. (In FIG. 7, jumper **724** crosses over
15 three of the loops in the coil **718** but does not make electrical contact with those loops. Furthermore, capacitive coupling between the jumper and such portions of the trace **722** is preferably negligible in comparison to capacitors **720a**, **720b**.) In this manner, the jumper **724** has the effect of providing two capacitors connected in series to the coil **718** substantially as shown in the schematic circuit diagram of FIG. 2b. Features of jumpers **424**, **524**, **624** discussed above are also applicable to jumper **724**.

20 The jumper **724**, which may be the only discrete circuit element of tuned RF circuit **716**, may be attached to the substrate **714** and conductive trace **722** while a web of substrate material is still intact, or after such web is slit or cut to provide the individual sensor tag **712**. The discrete circuit element is preferably carried by the substrate and disposed on a same side of the substrate **714** as conductive trace **722**.

25 In an alternative embodiment, one of the capacitors **720a**, **720b** may be eliminated by providing a direct electrical connection between the associated terminus of the jumper **724** and its corresponding contact pad of the conductive trace **722**. For example, capacitor **720a** may be eliminated by providing a direct electrical connection between terminus **724a** of the jumper and the contact pad **723a**. Alternatively, capacitor **720b** may be eliminated by providing a direct electrical connection between
30 terminus **724b** of the jumper and the contact pad **723b**. In either case the result is a tuned RF circuit in which the (sole) remaining capacitor is connected with an inductor as shown in the circuit diagram of FIG. 2a.

35 The reader will understand that the embodiments described in connection with FIGS. 4-7 are merely exemplary and are not intended to be limiting. Features of any given described sensor are intended to be applicable to other sensors, to the extent possible. For example, discrete or integrated capacitors described in connection with FIGS. 4 and 5 may also be incorporated into the circuits of FIGS. 6 and 7. Aspect ratios of the sensors and/or of the sensor coils can be adapted as desired, compare e.g. aspect ratios of FIG. 5 with those of FIG. 7. Furthermore, the sensors can be modified by incorporation

of other design features mentioned elsewhere herein, e.g., incorporation of an RFID integrated circuit chip into a given tuned RF circuit.

FIG. 8 is a schematic view of a portion of an exemplary wetness sensor **812** or sensor tag that shows additional detail with regard to a jumper attached to the substrate of the sensor. Sensor **812** thus includes a sensor substrate **814**, to which has been applied a conductive trace **822**. The substrate **814** is self-supporting, but it dissolves, swells, or otherwise degrades when contacted by water or another target fluid. The substrate **814** carries a tuned RF circuit **816**, of which the conductive trace **822** is a part. The trace **822** is not self-supporting. Trace **822** may include at least an inductive coil **818** and a contact pad **823b**.

A jumper **824** is attached to the substrate and/or to a portion of the conductive trace, such as with one or more adhesives (not shown) or by other suitable means. The jumper, which may be or comprise a layer of metal or other conductive material disposed on an electrically insulating substrate such as a layer of polymer material, couples directly or capacitively to the contact pad **823b** of the trace **822**. Furthermore, the jumper preferably avoids both direct contact and significant capacitive coupling to portions of the trace **822** that it crosses over. This can be done, in some embodiments, by providing the jumper with a conductor whose transverse dimension or width is greater at a terminus of the jumper compared to portions of the jumper that cross over the previously mentioned portions of the trace **822**. The widened conductor may form a tab at the jumper terminus, the tab preferably being aligned with or positioned to correspond to a contact pad **823b** of the conductive trace **822**, as shown in FIG. 8. Such alignment or positioning enhances capacitive coupling between the jumper terminus and the contact pad, or, if direct electrical contact is desired, simplifies the process of making direct electrical contact therebetween.

In the embodiment of FIG. 8, the jumper **824** comprises a jumper substrate **826** to which a conductor **828** has been applied, the conductor **828** being widened at the terminus **824b** to provide a tab **829b**. The jumper substrate **826** may, for example, comprise a thin flexible film or other suitable component. The jumper substrate **826** of FIG. 8 is depicted as being electrically insulative, such that the tab **829b** and pad **823b** form a capacitor **820b**.

The conductor **828** (including tab **829b**) may be applied directly to the exposed major surface of the substrate **826**, or, one or more intervening layers, e.g. to promote adhesion, may be included. The conductor **828** may be made by printing, coating, etching, electrodeposition, vapor deposition, thermographic transfer, and/or other known techniques, and may be composed of the same material as conductive trace **822**, or, in some embodiments, of a different material. Thus, for example, the conductor **828** of the jumper may be made of a metal or other suitable electrically conductive material, such as graphite and/or one or more conductive polymers, for example. Exemplary conductive materials include copper, silver, and/or nickel, but this list should not be construed as limiting. The conductor **828** may be provided on a suitable jumper substrate **826**, which may for example comprise a thin flexible film or other suitable component. Exemplary insulative materials that may be suitable for use as a jumper substrate may include melt-extrudable materials capable of being cast into flexible films, such as thermoplastic

polymers, polyethelene, polystyrene, polypropylene, polyester, polyvinylalcohol, or any of the dispersible, swellable, or dissolvable substrates described elsewhere herein.

In cases where a direct electrical connection is desired between the jumper **824** and the trace **822** at the terminus **824b**, a volume of conductive adhesive (not shown) may, for example, be applied in an amount sufficient to cover both the tab **829b** and the exposed portions of pad **823b**, such adhesive not only making a direct electrical connection between the tab and the pad, but also mechanically bonding the terminus **824b** of the jumper **824** to the substrate **814** through pad **823b**. Additionally or alternatively, an adhesive may be provided between the jumper **824** and the sensor substrate **814**/conductive trace **822** to bond the jumper **824** to the substrate.

The jumper arrangements discussed in connection with FIG. 8 may be utilized in any of the sensor embodiments discussed herein, as appropriate for the particular embodiment or portion thereof.

FIG. 9a is a schematic view of a portion of a wetness sensor **912** or sensor tag that also shows detail with regard to a jumper attached to the substrate of the sensor, where the jumper may be or comprise a layer of metal or other conductive material disposed on an insulating polymer substrate.

Sensor **912** thus includes a sensor substrate **914**, to which has been applied a conductive trace **922**. The trace **922** is widened locally to provide a pad **923b**. The substrate **914** is self-supporting, but it dissolves, swells, or otherwise degrades when contacted by water or another target fluid. The substrate **914** carries a tuned RF circuit, of which the conductive trace **922** is a part. The trace **922** is not self-supporting. Trace **922** may include at least an inductive coil and the contact pad **923b**.

A jumper **924** is shown attached to the substrate **914** via an adhesive layer **927**. The adhesive layer **927** as shown is electrically non-conductive; otherwise, if the layer **927** were conductive, it would cause short-circuiting between the different portions of the conductive trace **922** that it contacts. Representative non-conductive adhesive materials may be or include, for example, silicone, acrylate, urethane, tackified natural or synthetic rubber, or other adhesives that do not exhibit conductive properties in the frequency ranges described for this system. The jumper **924** includes a conductor **928** disposed on a jumper substrate **926**. The conductor **928** may have a given limited transverse dimension or width along the length of the jumper, but may be expanded or widened to form a tab **929b** at a terminus **924b** of the jumper. The widened tab **929b** forms a capacitor with pad **923b**, the value of the capacitance depending on the dielectric properties and thicknesses of the adhesive layer **927** and of the jumper substrate **926**, and on the relative geometry of the tab **929b** and pad **923b**. The jumper substrate **926** is assumed to be electrically insulative, but in some embodiments it may be electrically conductive, in which case the separate conductor **928** may be omitted from the jumper as redundant. An exemplary insulative jumper substrate **926** may, for example, comprise a flexible film formed from a melt-extrudable material, such as thermoplastic polymers, polyethelene, polystyrene, polypropylene, polyester, polyvinylalcohol, or any of the dispersible, swellable, or dissolvable substrates described elsewhere herein.

FIG. 9b is a schematic view of a portion of another wetness sensor **912b**, the figure again showing detail with regard to a jumper attached to the substrate of the sensor. Sensor **912b** is similar in many respects to sensor **912** of FIG. 9a, and like components are labeled with like reference numerals,

WO 2013/022742

PCT/US2012/049488

such components needing no further explanation beyond that provided above. Sensor **912b** differs from sensor **912** in that the jumper **924** has been flipped over such that its orientation relative to sensor substrate **914** and conductive trace **922** is reversed, compared to its orientation in FIG. 9a. Furthermore, increased pressure has been applied selectively in the vicinity of the jumper terminus **924b** so as to force the electrically insulative adhesive out of the region between tab **929b** and pad **923b**, such that direct electrical contact is made between the tab **929b** and pad **923b**. Such increased pressure has not been applied to the remaining portions of the jumper shown in the figure, so that the jumper **924** avoids direct electrical contact and significant capacitive coupling to the other portions of the conductive trace **922** shown in the figure. In some cases, a second terminus (not shown in FIG. 9b) at an end of the jumper **924** opposite terminus **924b** may likewise provide direct electrical contact between a similar tab of the conductor **928** and a similar pad of the conductive trace **922**, such that the jumper **924** provides direct electrical contact with the trace **922** at both ends of the jumper. In other cases, increased pressure may not be applied to the second terminus of the jumper **924**, such that insulative adhesive remains disposed between the second tab of the conductor **928** and the second pad of the trace **922**, and such that the jumper **924** provides direct electrical contact at the end or terminus of the jumper shown in FIG. 9b, but provides capacitive coupling at the opposite or second end or terminus of the jumper **924**.

The jumper arrangements discussed in connection with FIGS. 9a and 9b may be utilized in any of the sensor embodiments discussed herein, as appropriate for the particular embodiment or portion thereof.

FIGS. 10a and 10b are schematic side or cross-sectional views of sensor substrates for use in wetness sensors, the substrates each having a conductive trace of variable thickness. The combination of relatively thicker and relatively thinner portions of a given conductive trace can be used to advantage in any of the disclosed embodiments. Thicker portions of the conductive trace can, for example, help provide enhance electrical properties of the trace by helping to provide sufficiently high electrical conductivity and sufficiently low electrical resistivity of the trace. Thinner portions of the conductive trace can, for example, help provide regions of the trace that are more susceptible to breakage than the thicker regions when the sensor substrate begins to dissolve, swell, or otherwise degrade when contacted with the target fluid. Providing specific regions susceptible to breakage can help to provide more predictable or reliable failure mechanisms for the wetness sensors. Note that in exemplary embodiments, the conductive trace as a whole, considered by itself, remains non-self-supporting as described elsewhere herein, although in some cases some or all of the thicker regions of the conductive trace, considered individually or separately, may be self-supporting. Furthermore, in exemplary embodiments, both the thinner and the thicker portions of the trace are thinner than a thickness of the sensor substrate, and both the thinner and the thicker portions of the trace are preferably thinner than 1 micron or 100 nanometers, for example. In some cases, the thicker sections are at least two times the thickness of the thinner sections. Other thickness relationships are also contemplated, keeping in mind the tradeoff between frangibility and electrical performance of the circuit.

Turning then to FIG. 10a, we see there an article **1024a** for use in the disclosed wetness sensors, the article **1024a** including a sensor substrate **1026** that is self-supporting, that is adapted to carry a tuned

RF circuit, and that is adapted to dissolve, swell, or otherwise degrade when contacted with a target fluid. A conductive trace **1028a** has been formed on the substrate **1026**, e.g., by printing, coating, etching, electrodeposition, vapor deposition, thermographic transfer, and/or other known patterning techniques. The trace **1028a** may be composed of a metal or other suitable electrically conductive materials, such as graphite and/or one or more conductive polymers, for example. The trace **1028a** is so mechanically delicate that it is unable to maintain its physical integrity in the absence of the supporting substrate **1026**. Trace **1028a**, when considered by itself, is thus not self-supporting, even though in some cases some or all of the thicker regions of the conductive trace, considered individually or separately, may be self-supporting. Trace **1028a** is typically patterned so as to form at least an inductive coil of the RF circuit.

As shown, the trace **1028a** exhibits a variable thickness. Trace **1028a** thus includes both thicker portions **1028a-1** and thinner portions **1028a-2**. The variable thickness can be provided using a variety of fabrication techniques. For example, if thin film evaporation is used to form the trace, baffles or shields can be employed to reduce the film thickness in selected areas. If printing is used to form the trace, multiple passes can be employed, or printing parameters can be manipulated, to build up the film thickness in selected areas. If an etching process is used to form the trace, selective etching can be used to reduce the film thickness in selected areas.

The article **1024b** of FIG. 10b is another article suitable for use in the disclosed wetness sensors, and the thickness profile of the conductive trace is similar in some respects to that of article **1024a** of FIG. 10a. The article **1024b** includes a sensor substrate **1026b** that is self-supporting, that is adapted to carry a tuned RF circuit, and that is adapted to dissolve, swell, or otherwise degrade when contacted with a target fluid. A conductive trace **1028b** has been formed on the substrate **1026b**, e.g., by printing, coating, etching, electrodeposition, vapor deposition, thermographic transfer, and/or other known patterning techniques. The trace **1028b** may be composed of a metal or other suitable material, as discussed elsewhere herein. The trace **1028b** is applied sufficiently heavy or thick so that that the metal is thicker in the recessed areas of the profiled backing and thinner in the raised areas of the profiled backing, and does not just follow the contours of the profiled backing, especially when applied by electrodeposition or vapor deposition. Furthermore, the trace **1028b** is not self-supporting as a whole, and particularly not the thinner portions thereof. Trace **1028b** is typically patterned so as to form at least an inductive coil of the RF circuit.

The trace **1028b** exhibits a variable thickness. The thickness variation pattern or profile is similar to that of trace **1028a** (FIG. 10a), but the structured surface **1026b-1** corresponding to the thickness variation is an interior or “buried” interface between the trace **1028b** and the substrate **1026b**, rather than being an exterior or exposed surface of the trace **1028b**. The result, however, is again that the trace **1028b** exhibits a variable thickness, including both thicker portions **1028b-1** and thinner portions **1028b-2**. The variable thickness can be provided using a variety of fabrication techniques. For example, before forming the trace **1028b** on the substrate **1026b**, the exposed surface of the substrate can be microstructured to form surface **1026b-1** e.g. by embossing or by using a continuous cast and cure (3C) process, for example. Conductive material that forms trace **1028b** can then be deposited onto the

WO 2013/022742

PCT/US2012/049488

structured surface **1026b-1** by printing or by other methods to produce a trace whose exposed surface is substantially flat, yet whose thickness changes along the length of the trace.

Preferably, the thickness profiles provide thinned regions that are separated from each other by substantially longer lengths of thicker regions. Such designs advantageously maximize the conductivity (and minimize the resistivity) of the trace, while still providing a plurality of spaced-apart thinned regions to promote RF circuit failure if the target fluid contacts the substrate. Buried interface designs such as that of FIG. 10b are advantageous from a manufacturing standpoint compared to exposed structured surface designs such as that of FIG. 10a.

FIG. 10c is a schematic plan view of another article **1024c** suitable for use in the disclosed wetness sensors. The article **1024c** includes a sensor substrate **1026** and a conductive trace **1028c** applied to the substrate. Characteristics of sensor substrates and conductive traces discussed elsewhere herein are equally applicable to those of FIG. 10c. Similar to the articles of FIGS. 10a and 10b, article **1024c** provides distinct regions of the conductive trace that makes the trace more susceptible to breakage in such regions. In FIG. 10c, these regions are characterized by a reduction in the transverse in-plane dimension, or width, of the trace in a sequence of spaced-apart regions. Consequently, the trace **1028c** has a variable width. Relatively narrower portions **1028c-2** are distributed along the length of the trace **1028c**, separated by relatively wider portions **1028c-1** of the trace. The wider portions enhance the electrical conductivity and reduce the electrical resistivity of the trace.

The reader will understand that the embodiments of FIGS. 10a through 10c are meant to be exemplary and not limiting. Design variations are contemplated. Thickness or width profiles other than V-shaped or rectangle-shaped features can be used. The relative spacing of the reduced thickness or reduced width regions can be selected as desired. In some cases, only one such reduced thickness or reduced width region may be used along the entire length of the trace. Furthermore, features of the different embodiments are intended to be mixed and matched. Embodiments may incorporate both one or more reduced thickness regions and one or more reduced width regions in a given conductive trace. In some respects, variations in thickness of the trace are more advantageous than variations in width of the trace because, given the surface area constraints of a given system, increasing the thickness of the trace will result in a larger change in electrical impedance than increasing the width of the trace. Exemplary thicknesses used for the conductive trace are less than the skin depth of the electrical signal at the RF operating frequency, and increasing the thickness of the trace allows more area for the RF signal to travel.

EXAMPLES

Example 1

A sheet of polyvinyl alcohol (PVA) film (available as “Monosol M8630” from Monosol, LLC, Portage, Indiana, USA) having a measured thickness of two mils (about 51 micrometers) was used as the self-supporting substrate. The sheet of PVA film was held down on a silk screening table using vacuum. Placed against this sheet was a 157 mesh silk screen, the silk screen having imaged therein an array of

patterns corresponding to the printed circuit elements **1116** of FIG. 11. The particular pattern of the example was an inductive coil having about six turns arranged in a spiral. The conductive ink was then pattern-wise applied to the PVA sheet through the silk screen by applying even pressure to a squeegee. The silk screen was then removed, yielding the printed sheet **1110** as generally depicted in FIG. 11. The printed sheet was allowed to air dry overnight on a drying rack. The procedure was repeated for the application of a total of three different conductive inks (CI-2001, CI-5001, CI-1001 available from ECM Corporation, Delaware, Ohio, USA), yielding three printed sheets having nominally the same pattern but using different conductive materials.

The printing technique yielded the overall pattern of the circuit element **1116** shown in FIGS. 11 and 12. Viewing of the circuit element under a microscope revealed that the edges of the trace were jagged. The width of the individual portions of the trace was nominally about 0.5 mm, and the thickness of the trace was measured to be about 12 microns.

Without attaching any individual capacitors or jumpers to the conductive traces, the impedance of the circuit element was measured using an Agilent 4294A Precision Impedance Analyzer with a 42941A Impedance Probe (available from Agilent Technologies, Santa Clara, California, USA). The instrument was swept from 8 MHz to 15 MHz and the probe was calibrated using open and short calibration standards. On the impedance analyzer a mark was placed at 13.56 MHz to display the values of the real and imaginary parts of the impedance. The sample and probe were placed on a non-conductive surface and the probe was used to measure the impedance across the two open terminals of the trace. The results for the different conductive inks are provided in Table 1:

Table 1

Conductive Ink	<i>Resistance (ohms)</i>
CI-1001 (conductive silver ink)	<i>400</i>
CI-2001 (conductive carbon black graphite)	<i>4000</i>
<i>CI-5001 (conductive carbon black nickel)</i>	<i>8000</i>

Individual tags were made by cutting the printed sheets **1110** as described above to produce individual sensor-sized pieces, one of which is shown in the photograph of FIG. 12. In the photograph, the reference grid, which can be seen through the PVA sheet, is an array of 25.4 mm by 25.4 mm (1 inch by 1 inch) squares. These tags, with their conductive trace in the form of inductors, were suitable as a basis for forming tuned RF circuits as disclosed herein, provided such tags were combined with one or more appropriate capacitors and jumpers.

Without applying such components, the impedance of a tag made using the CI-1001 conductive ink was measured while exposing the tag to water. The impedance measurement was made using the same Agilent 4294A Precision Impedance Analyzer with the 42941A Impedance Probe. As before, the instrument was swept from 8 MHz to 15 MHz, and the probe was calibrated using open and short calibration standards. On the impedance analyzer a mark was placed at 13.56 MHz to display the values of the real and imaginary parts of the impedance. The sample and probe were placed on a non-conductive

surface, and the probe was used to measure the impedance across the two open terminals of the trace. Tap water (0.5 mL) was poured onto the tag in a single portion. The PVA substrate subsequently disintegrated, creating breaks in the conductive trace of the tag. Over a period of 10 seconds starting from the addition of water, the real impedance measurement changed from 400 ohms to over 3,000 ohms.

5

Examples 2-10

Examples 2 through 10 describe the fabrication of strip-shaped and U-shaped samples having a layer of conductive material completely covering one major surface or side of the respective strip-shaped or U-shaped substrate. Such samples may be used, for example, as jumpers in the disclosed tuned RF circuits. However, the reader will understand that the design of such samples can be readily modified, e.g. by suitably patterning the electrically conductive material to provide tags having one or more inductive coil(s) and/or other circuit element(s) carried by a substrate, such a tag representing or providing at least a portion of a tuned RF circuit. Such a tag would have analogous electrical properties (before and after wetting) as those reported below for the samples of Examples 2-10.

15

Example 2

Individual sheets of polyvinyl alcohol (PVA) film (available as “Monosol M8630” from Monosol, LLC, Portage, Indiana, USA) having measured thicknesses of 2, 4, and 6 mils (about 51, 102, and 153 micrometers respectively) were used as self-supporting substrates. Silver films were coated onto 127 mm by 178 mm samples of the PVA film substrates by magnetron physical vapor deposition. The silver films were sputter deposited from a silver metal target. The PVA substrates were placed on a substrate holder set up inside a vacuum chamber with a sputtering silver target located at a height of 178 mm above the substrate holder. After the chamber was evacuated to 1×10^{-5} torr base pressure, sputter gas argon was admitted inside the chamber at a flow rate of 50 sccm (standard cubic centimeter per minute) using a mass flow controller. The total pressure of the chamber was adjusted to 2 milliTorr. Sputtering was initiated using a DC power supply at a constant power level of 0.10 kilowatts. The sputter duration was varied to produce samples having different silver film thickness. For example, coating using a power level of 0.10 kilowatts for 7 minutes produced a sample with a silver film thickness of 140 nm. The substrate was not heated and was kept at room temperature. The thickness of the silver film deposited on the samples was determined by measuring the thickness of silver deposited on silicon wafers that were placed next to the samples during the coating process. The thickness of silver deposited on the wafers was determined using a KLA Tencor Model P-15 Profilometer (available from KLA Tencor Corporation, San Jose, California, USA).

Individual strip-shaped samples (having dimensions of 25 mm by 152 mm) were cut from the silver coated PVA substrate sheet. The individual samples were tested for disintegration and dissolution of the substrate using the following method. A 500 milliliter beaker filled with saline solution (0.9% NaCl) was maintained at ambient temperature (20.5 °C) and agitated with stirring. The individual samples of the silver coated substrate were immersed in the saline solution so that the entire sample was

WO 2013/022742

PCT/US2012/049488

covered by liquid. The time required for sample disintegration and sample dissolution was measured in seconds. Sample disintegration was defined as the point where the substrate film began to break apart, creating breaks in the silver coating. Dissolution was defined as the point where the substrate film totally dissolved in the liquid, leaving small particles of silver suspended in the liquid. The results are reported

5 in Table 2.

Table 2

Thickness of Silver Coating (nm)	Thickness of PVA Substrate (mil)	Disintegration Time (seconds)	Dissolution time (seconds)
40	2	12	25
90	2	13	29
140	2	15	40
140	4	780	not determined
140	6	>1080	not determined

10 Example 3

A sheet of PVA film (available as “Monosol M8630” from Monosol, LLC, Portage, Indiana, USA) having a measured thickness of 2 mils (about 51 micrometers) was sputter deposited with silver by magnetron physical vapor deposition at a thickness of 40 nm according to the procedure described in Example 2. A sample strip (25 mm by 152 mm) was cut from the silver coated PVA substrate sheet and

15 placed on a non-conductive surface. The sample was tested for resistance before and after wetting with a saline solution. Using a Simpson Model 260 Ohmmeter (Simpson Electric, Lac du Flambeau, Wisconsin, USA), the test leads of the ohmmeter were attached to opposite ends of the sample. The meter was set to record measurements over a range of 0 to 2000 ohms. An initial resistance reading of about 0 ohms was measured. After pouring a single portion of saline solution (0.5 mL of 0.9 % NaCl) onto the center region

20 of the sample, the silver coated PVA film disintegrated, creating breaks in the silver coating. The resistance measurement changed from 0 ohms to 2000 ohms (the maximum instrument setting) over a period of 10 seconds.

Example 4

25 The same procedure as described in Example 3 was followed, except that the saline solution was replaced with 1.0 mL of a simulated wound fluid solution. The simulated wound fluid solution was prepared by dissolving sodium chloride (2.07 g) and calcium chloride (0.07 g) in deionized water (247.9 g) according to the procedure described in U.S. Patent Application Publication US 2011/0040289 (Canada et al.). The sample was tested for resistance before and after exposure to the simulated wound

30 fluid. Using a Smart Electrician Model 364-5017 Digital Meter (available from Menards Corporation, Eau Claire, Wisconsin, USA), the test leads of the ohmmeter were attached to opposite ends of the sample. The meter was set to record measurements over a range of 0 to 300 ohms. An initial resistance reading of 0 ohms was measured. After pouring a single portion of simulated wound fluid solution (1.0 mL) onto the center of the sample, the silver coated PVA film disintegrated, creating breaks in the silver

coating. The resistance measurement changed from 0 ohms to 300 ohms (the maximum instrument setting) over a period of 11 seconds.

Example 5

5 A square sheet (76 mm by 76 mm) of expanded polystyrene foam (EPF) having an initial measured thickness of 1.8 mm was compressed at 170 °C and 34,500 kPa (5000 psi) for 18 seconds using a Model 3912 Carver Hydraulic Press (Carver Corporation, Wabash, Indiana, USA) to provide a 0.23 mm thick sample. The compressed sheet of EPF was used as a self-supporting substrate. The entire surface of the EPF sheet was then flood coated with CI-1001 conductive ink (available from ECM Corporation,
10 Delaware, Ohio, USA) using a Mayer rod (number 3). The coating thickness was about 1.7 grams per square meter (gsm). The printed sheet was placed in an oven at 50 °C for 30 minutes. After cooling to ambient temperature, a 76 mm by 13 mm strip was cut from the printed EPF sheet. The strip-shaped sample was tested for resistance before and after exposure to unleaded gasoline. Using the Smart Electrician Model 364-5017 Digital Meter, the test leads of the ohmmeter were attached to opposite ends
15 of the sample. The meter was set to record measurements over a range of 0 to 300 ohms. An initial resistance reading of 0 ohms was measured. The sample with leads attached was placed in a glass petri dish, and unleaded gasoline (10 mL) was added to the petri dish to create a pool of gasoline about 6 mm in depth. On initial set-up, the sample with leads attached was carefully flexed so that the leads would not be in contact with the gasoline solvent. The coated EPF strip disintegrated after contact with the gasoline,
20 creating breaks in the conductive ink coating. Over a period of 44 seconds starting from the addition of the gasoline to the sample, the resistance measurement changed from 0 ohms to 300 ohms (the maximum instrument setting).

Example 6

25 An adult sized mannequin designed for the testing of absorbent articles (available from Marketing Technology Service, Inc., Kalamazoo, Michigan, USA) was obtained. The mannequin was arranged in a standing position. A Masterflex Peristaltic L/S Pump (available from Cole-Parmer, Vernon Hills, Illinois, USA) was used to pump saline solution (0.9% NaCl) through the male or female outlet of the mannequin. The mannequin was fitted with a Medline Comfort-Aire Unisex Disposable Brief diaper having a hip size
30 of 40-50 inches (available from Medline Industries, Mundelein, Illinois, USA). The sensor part of the assembly was prepared from a sheet of 305 mm by 254 mm PVA film (2-mil thickness) sputter coated on one side with silver (40 nm thickness) according to the procedure described in Example 2. The film was then cut using a laser to provide a generally U-shaped sample, the shape shown in plan view in FIG. 12a. In reference to that figure, the length L1 of the two parallel sides was about 190 mm, the length L2 of the
35 other side was about 15 mm, and the width w was about 5 mm. A laminate was prepared by attaching the sample (silver side up) to tissue paper (220 mm by 40 mm sheet) using a minimum amount of a spray adhesive (available as “3M™ Super 77™ Multipurpose Adhesive” from 3M Company, Maplewood, Minnesota, USA). The sample was positioned in the center of the tissue paper so that about 25 mm of the open ends of the two parallel sides extended beyond the edge of the tissue paper. The laminate was

WO 2013/022742

PCT/US2012/049488

attached with the same spray adhesive to the backsheet on the inside front portion of the diaper at a position 90 mm from the top of the waist band. The sample side of the laminate was directed toward the mannequin. A small hole was cut through the back sheet of the diaper so that the two ends of the U-shaped sample that extended beyond the tissue paper backing could be inserted through the hole and

5 attached using alligator clips to an Agilent 4294A Precision Impedance Analyzer (available from Agilent Technologies, Santa Clara, California, USA). The operation of the pump and recording of impedance data was automated using LabView software (available from National Instruments, Austin, Texas, USA).

Saline solution was added to the diaper through the inlet port in the mannequin at the set rate of 4 mL/sec. At an elapsed time of about 40 seconds, a shift in the impedance measurement from 0 ohms to

10 about 200 ohms was detected. At an elapsed time of 155 seconds, a further shift in impedance to greater than 1000 ohms was detected. Measurements of impedance versus time are presented in Table 3. Visual examination of the laminate at the end of the experiment showed that the PVA substrate had dissolved, destroying the integrity of the sensor. Similar results were obtained using either the male or female outlet port.

Table 3

Elapsed Time (seconds)	Real Impedance (ohms)	Imaginary Impedance (ohms)	Total Liquid (ml)
0.5	0	0	2
5	22.0	-14.7	20
15	21.6	-14.1	60
25	21.2	-13.9	100
35	24.2	-14.4	140
45	217.2	-60.6	180
55	318.3	-86.7	220
65	309.4	-79.4	260
75	359.2	-100.4	300
85	362.1	-102.0	340
95	411.0	-125.1	380
105	411.4	-125.5	420
115	422.0	-128.0	460
125	431.9	-131.0	500
135	671.4	-332.3	540
145	794.1	-435.2	580
155	1012.8	-621.7	620
165	1066.2	-650.3	658

Example 7

Samples with conductive traces having non-uniform thickness were prepared from sheets of PVA film (2-mil thickness) sputter coated on one side with silver according to the procedure described in

20 Example 2, except that, in order to obtain a non-uniform thickness of the conductive material, a pattern template was placed over the film to mask or prevent specified regions of the PVA substrate from being coated. With the pattern template in place, the PVA film was sputter coated to provide a first coating of

silver (40 nm thickness). The template was then removed, and a second coating of silver (40 nm thickness) was applied. The result was a pattern in which some regions of the film were coated with silver of 80 nm thickness, and the remaining regions of the film were coated with silver of only 40 nm thickness.

5 The coated film was cut using a laser to prepare U-shaped samples as shown generally in FIG. 12a, where the length L1 of the two parallel sides was about 99 mm, the length L2 of the other side was about 15 mm, and the width w was about 5 mm.

Five samples (referred to herein as Samples 7a through 7e) containing different patterns of variable thickness in the conductive silver layer were prepared. Two samples (referred to herein as
10 Samples 7f and 7g) were prepared having a conductive silver layer of uniform thickness.

In Sample 7a, the conductive layer contained four regions of 80 nm thick coated silver, with each region having an area of 8 mm by 5 mm. The four regions were equally positioned on the two parallel sides of the U-shaped substrate (2 regions on each side) starting at positions 5 mm from the upper (closed) end of the shape (as seen from the perspective of FIG. 12a) and at the lower (open) end of the shape. For
15 Sample 7a, 16% of the total area of the conductive layer had a silver coating of 80 nm thickness, and the remaining area had a silver coating of 40 nm thickness.

In Sample 7b, the conductive layer contained eight regions of 80 nm thick coated silver with each region having an area defined by a square of 5 mm by 5 mm. The eight regions were equally positioned on the two parallel sides of the U-shaped substrate (4 regions on each side) starting at positions 10 mm
20 from the upper (closed) end of the shape (refer to FIG. 12a) and 5 mm from the lower (open) end of the shape. For Sample 7b, 20% of the total area of the conductive layer had a silver coating of 80 nm thickness, and the remaining area had a silver coating of 40 nm thickness.

In Sample 7c, the conductive layer contained ten regions of 80 nm thick coated silver with each region having an area defined by a square of 5 mm by 5 mm. The ten regions were equally positioned on
25 the two parallel sides of the U-shaped substrate (5 regions on each side) starting at positions 8 mm from the upper (closed) end of the shape (refer to FIG. 12a) and 2 mm from the lower (open) end of the shape. For Sample 7c, 25% of the total area of the conductive layer had a silver coating of 80 nm thickness and the remaining area had a silver coating of 40 nm thickness.

In Sensor Sample 7d, the conductive layer contained sixteen regions of 80 nm thick coated silver
30 with each region having an area defined by a square of 5 mm by 5 mm. The sixteen regions were equally positioned on the two parallel sides of the U-shaped substrate (8 regions on each side) starting at positions 8 mm from the upper (closed) end of the shape (refer to FIG. 12a) and 5 mm from the lower (open) end of the shape. For Sample 7d, 40% of the total area of the conductive layer had a silver coating of 80 nm thickness and the remaining area had a silver coating of 40 nm thickness.

35 In Sensor Sample 7e, the conductive layer contained eight regions of 40 nm thick coated silver with each region having an area defined by a square of 5 mm by 5 mm. The eight regions were equally positioned on the two parallel sides of the U-shaped substrate (4 regions on each side) starting at positions 10 mm from the upper (closed) end of the shape (refer to FIG. 12a) and 5 mm from the lower (open) end

of the shape. For Sample 7e, 20% of the total area of the conductive layer had a silver coating of 40 nm thickness and the remaining area had a silver coating of 80 nm thickness.

Sample 7f was prepared with a uniform silver coating of 40 nm thickness, and Sample 7g was prepared with a uniform silver coating of 80 nm thickness.

5 Impedance measurements for Samples 7a through 7f were determined using an Agilent 4294A Precision Impedance Analyzer with a 42941A Impedance Probe (available from Agilent Technologies, Santa Clara, California, USA). The instrument was swept from 8 MHz to 15 MHz and the probe was calibrated using open and short calibration standards. On the impedance analyzer a mark was placed at 13.56 MHz to display the values of the real and imaginary parts of the impedance. The sample and probe
10 were placed on a non-conductive surface, and impedance was measured across the open end of the sample (i.e., the lower ends of the shape shown in FIG. 12a) by attaching the probe about 1 mm from the ends of the U-shaped sample. The results are reported in Table 4 as the average of six measurements.

Sample 7e was placed on a dry paper towel (trade designation “WypAll”, available from Kimberly-Clark Corporation, Neenah, WI) and the open ends of the conductive sample were attached to
15 the leads of the impedance probe. Tap water (1.0 mL) was placed directly on a portion of Sample 7e that contained regions of both thick silver coating (80 nm) and thin silver coating (40 nm). Disintegration of the thin coated region was observed at 13 seconds after the addition of water, while the thick coated region began to disintegrate at 30 seconds after the addition of water. The initial real impedance measurement of 18 ohms began to shift beginning at 9 seconds after the addition of water. At the 13
20 second time point, where disintegration of the thin coated region was observed, the real impedance measurement was greater than 1000 ohms.

Table 4

Sensor Sample	Real Impedance (ohms)	Imaginary Impedance (ohms)
7a	43	4.8
7b	52.5	4
7c	55.5	3.5
7d	42	4.7
7e	18	5
7f	65	4
7g	17	5

25 Example 8

Sample 7f described in Example 7 was attached with adhesive tape (under the trade designation Scotch® Transparent Tape, available from 3M Company, Maplewood, Minnesota, USA) to a 102 mm by 102 mm piece of dry wall (available from Lafarge North America, Washington, DC). The impedance measurements were determined using an Agilent 4294A Precision Impedance Analyzer with a 42941A
30 Impedance Probe (available from Agilent Technologies, Santa Clara, California, USA). The instrument was swept from 8 MHz to 15 MHz and the probe was calibrated using open and short calibration standards. On the impedance analyzer a mark was placed at 13.56 MHz to display the values of the real

and imaginary parts of the impedance. The leads of the probe were attached to the open end of the trace and the initial impedance value was measured for a dry sample. An initial impedance of the dry sample was measured. The sample attached to dry wall was submerged into a tray containing tap water so that about 25.4 mm (1 inch) of the sample (starting from the end opposite from the attachment of the leads) was under water. An impedance shift was recorded within 5 seconds of submersion of the sample into the water. At 30 seconds, the silver coated PVA film disintegrated, creating breaks in the silver coating. The impedance measurements for the dry sample and the sample after submersion in tap water for 30 seconds are presented in Table 5.

Table 5

Sample	Initial Real Impedance (dry sample) (ohms)	Initial Imaginary Impedance (dry sample) (ohms)	Final Real Impedance (wet sample) (ohms)	Final Imaginary Impedance (wet sample) (ohms)
Sample 7f attached to drywall	15	6	1000	-1400

Example 9

A sheet of polyvinyl alcohol (PVA) film (available as Monosol M8630 from Monosol, LLC, Portage, Indiana, USA) having a measured thickness of 2 mils (about 51 micrometers) was sputter deposited with silver by magnetron physical vapor deposition according to the procedure described in Example 2. Three individual samples were prepared having silver coated at thicknesses of 141 nm, 187 nm, and 280 nm. Each sample of coated film was cut using a laser to provide a generally U-shaped sample, the shape shown in FIG. 12a. In reference to that figure, the length L1 of the two parallel sides was about 190 mm, the length L2 of the other side was about 15 mm, and the width w was about 5 mm. Impedance measurements were determined using an Agilent 4294A Precision Impedance Analyzer with a 42941A Impedance Probe (available from Agilent Technologies, Santa Clara, California, USA). The instrument was swept from 8 MHz to 15 MHz and the probe was calibrated using open and short calibration standards. On the impedance analyzer a mark was placed at 13.56 MHz to display the values of the real and imaginary parts of the impedance. The sample and probe were placed on a non-conductive surface and impedance was measured across the open end of the sample (i.e., the lower ends of the shape shown in FIG. 12a) by attaching the probe about 1 mm from the ends of the U-shaped sample. An initial impedance of the dry sample was measured. After adding 3.0 mL of artificial urine (available from Ward's Natural Science, Rochester, New York, USA) dropwise to the sample, an impedance shift was recorded within seconds of adding the liquid. Initial and final impedance measurements are reported for the three samples in Table 6.

Table 6

Silver thickness (nm)	Initial Real Impedance (dry sample) (ohms)	Initial Imaginary Impedance (dry sample) (ohms)	Final Real Impedance (wet sample) (ohms)	Final Imaginary Impedance (wet sample) (ohms)
280	8.2	84.0	5740	-75.0
187	7.9	87.0	4300	-72.6

141	7.2	78.0	3000	-79.6
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Example 10-Prophetic

A sheet of polyvinyl alcohol (PVA) having a thickness of 2 mils (about 51 micrometers) can be fabricated to have thinner and thicker regions as depicted in FIG. 10b and can be used as the self-supporting substrate **1026b**. Fabrication (for example by embossing) can form the depressed microstructured surface **1026b-1** at a depth of 40 nm, for example. The substrate can be flood coated with conductive ink to provide 40 nm ('thin') regions of conductive material (**1028b-2**) and 80 nm ('thick') regions of conductive material (**1028b-1**). The resulting exposed surface of the conductive ink coating may be substantially flat. The coated film can be cut using a laser to provide a generally U-shaped sample, substantially as shown in FIG. 12a. In reference to that figure, the length L1 of the two parallel sides may be 190 mm, the length L2 of the other side may be 15 mm, and the width w may be 5 mm. Any pattern of thick and thin regions may be used as long as at least one thin region (**1028b-2**) is present in the sensor. Impedance measurements can be made with any suitable impedance analyzer or ohmmeter. The sample and probe can be placed on a non-conductive surface, and the impedance may be continuously measured across the open end of the conductive sample by attaching the probe at the ends of the U-shaped sample. Water, saline solution, artificial urine, or simulated wound fluid can be added to the sample. The sample can be measured for impedance before and after wetting. The substrate may be observed to disintegrate (creating breaks in the trace) and a shift in the impedance by a factor of 100 to 1000 can be measured.

FURTHER EMBODIMENTS AND APPLICATIONS

FIG. 13 is a schematic diagram showing different end-use applications of the disclosed wetness sensors **1312**. The depicted applications are merely exemplary, and are not intended to be limiting. On one application, the wetness sensor **1312** is inserted or otherwise incorporated into an absorbent garment such as a diaper **1360**. In another application, the sensor **1312** is inserted or otherwise incorporated into a roof **1350**, building, or similar structure. The sensor **1312** may for example be positioned underneath shingles, tiles, or other roofing materials in a place that would normally be expected to remain dry, but where the presence of moisture would be important to be aware of. In either case, wetness of the garment, building, or other article may be conveniently detected by remote monitoring of the sensor **1312** as discussed above.

The wetness sensor **1312** can be beneficially used in other applications, discussed above, in which it is desirable to detect wetness but difficult to visually or otherwise directly observe the wetness. The sensor **1312** may for example be incorporated into or otherwise attached to construction-related articles such as wall board, insulation, flooring, and roofing, as well as fittings and support structures to detect leakage from pipes underground, beneath floors, behind walls, or above ceilings, for example. Other applications may include incorporating the wetness sensor **1312** into packages or boxes to detect leakage or thawing, e.g. for medical or automotive applications, for example.

FIG. 14a is a schematic view of a diaper **1460** or similar incontinence or absorbent garment, and FIG. 14b is a schematic cross-sectional view taken along lines 14b-14b in FIG. 14a. The diaper includes a liquid-permeable inner sheet **1462**, a liquid-impermeable outer sheet **1464**, and an absorbent material **1466** trapped between the sheets **1462**, **1464**, and optionally limited to an absorbent region **1467**. The
5 diaper **1460** may also include elastic members **1468** and closure elements **1470** such as adhesive tape or hook-and-loop fasteners. The diaper has also been assembled in such a way as to include a wetness sensor **1412** at a position that is likely to become wet or soiled. The sensor **1412**, which may be or comprise any of the wetness sensors disclosed herein, is disposed between the sheets **1462**, **1464**, and may be adhered to either such sheet using an adhesive, ultrasonic welding, or by other known attachment
10 techniques. If the sensor **1412** is disposed between the liquid-impermeable sheet **1464** and the absorbent material **1466**, it will degrade when the material **1466** is saturated and will not be triggered by the release of only a small amount of target fluid. The wetness of the diaper may be conveniently detected by remote monitoring of the sensor **1412** as discussed above.

In some cases it may be advantageous to design the sensor **1412** to have a large aspect ratio, e.g.,
15 even larger than those of FIGS. 4 and 6, by significantly lengthening the jumper (**424**, **624**). With such an elongated sensor, the antenna or inductor (e.g., **418**, **618**) can be placed within the diaper at a position that is not likely to become wet or soiled, e.g., at a position closer to the waistband, while the remainder of the sensor (and in particular at least a portion of the jumper) may be placed at the position that is likely to become wet or soiled. Such placement of the antenna or inductor may also be used to improve
20 communications (e.g., signal-to-noise ratio) with the reader device.

In alternative embodiments, any of the wetness sensors disclosed herein may additionally include a skin-compatible adhesive, such as a gentle silicone skin adhesive, on an outer surface of the sensor or on a portion of such outer surface. A sensor configured in this way may be applied directly to the skin of a subject rather than being manufactured into a diaper, brief, or other garment or article. Such an approach
25 can potentially reduce overall cost and encourage implementation by working with existing garments and avoiding the need for specially manufactured garments or articles. The adhesive may also be formulated to be repositionable such that the attachment point of the sensor to the subject may be readily changed, and/or such that the sensor may be reused on a given subject between changings, for example. The adhesive may be applied selectively to a portion of the sensor at the antenna or inductor (e.g., **418**, **618**),
30 and, particularly if the wetness sensor is elongated in shape, the remainder of the sensor may comprise no skin-compatible adhesive. In such an embodiment, the antenna or inductor portion of the sensor may be attached to the subject at or above the waist, for example, and the remainder of the sensor may be allowed to simply hang down into the diaper or brief as appropriate.

Any known skin-compatible adhesives may be used in such embodiments. In one embodiment, a
35 skin-compatible adhesive may be prepared by blending 100 parts of polydimethylsiloxane (e.g., Xiameter brand OHX-4070) polymer with 30 parts MQ resin (e.g., type Belsil TMS 803, available from Wacker Chemie AG) to obtain a homogeneous mixture. The adhesive solution may be coated onto an outer surface of a wetness sensor (or a web containing numerous wetness sensors, see e.g. FIG. 1) using a

WO 2013/022742

PCT/US2012/049488

simple knife coater or by other known means at a suitable thickness, e.g. 0.002 inches to 0.004 inches. Such an adhesive may be crosslinked by exposure to a suitable e-beam source, for example. Preferably, the skin-compatible adhesive is substantially electrically non-conductive such that it does not detrimentally affect the operation of the tuned RF circuit, even when applied directly to conductive traces of the sensor.

The sensors described herein may be especially useful when used in an infrastructure-based wetness monitoring system, e.g., a system that detects wetness in incontinent long-term care facility patients. In such a system, the state of the fluid sensor changes with the wetness condition of the personal hygiene article or other article to which it is attached, and the state of the sensor is communicated to a reader when interrogated. That information may then be communicated by the reader via a network connection to a central storage location. The database may store the information with a timestamp and/or other identification information. This information can then be post-processed using custom algorithms. Continence-related data from a multiplicity of sites can be collated, packaged, extracted, correlated, integrated, and analyzed for use by hospitals, care institutions, manufacturers of absorbent articles, governments, health insurers, and so forth. Exemplary wetness monitoring systems include but are not limited to the systems described in U.S. 7,250,547 (Hofmeister), U.S. 7,977,529 (Bergman), U.S. 2007/0270774 (Bergman) WO 2007/128038 (Bergman), WO 96/14813 (Bergman) and WO 2011/054045 (Bergman), all of which are incorporated herein by reference. The wetness monitoring systems are not limited to urine detection for incontinent patients, but also have applicability in the detection, monitoring, and management of conditions in which other fluids and exudates from the body (or from other sources) may be present, including wound management.

An exemplary system for monitoring incontinence in one or multiple subjects includes one or more fluid sensors installed into or on an item for which it is desired to monitor the presence of fluid, a reader that includes appropriate electronics and an antenna to couple the reader to the sensor(s), a network connection, and a database for storage and analysis of data. Another system comprises a display means; input means that may be operable by a user; one or more transmitters, each transmitter being associated with one or more subjects being monitored; the one or more transmitters being configured to transmit signals containing at least continence-related data for the multiple subjects, wherein the continence-related data has been obtained over time from one or more wetness sensor such as those disclosed herein that may be associated with an absorbent article worn by each respective subject; a receiver unit configured to receive signals from the one or more transmitters; and processing means in communication with at least the receiver unit, the processing means including a display processor configured to process the received signals and communicate display information to the display means for display of a visual representation of continence-related information derived from the wetness sensors attached to absorbent articles worn by the subjects being monitored.

Sensors may be of different types, e.g. where they have different functionality. In addition to wetness sensors, the sensors may include functionality for sensing one or more of temperature, pH, pressure, odor, bioanalytes, chemical or biological markers, and other indicators of the wellbeing of the

WO 2013/022742

PCT/US2012/049488

subject. Potential sensors include sensors to detect for the presence of water, urine, blood, other liquid solvents, or elements therein. In addition, sensors for monitoring vital signs such ECG, blood glucose levels, blood pressure, pulse, etc. may be combined with the disclosed wetness sensors. An extensive list of clinically relevant medical conditions may be recognized by the detection of a number of metabolites, chemicals and ions, as well as other substances and cells of different types, in urine. Such materials as nitrites, amino acids, Beta-2 microglobulin, such measurements as pH, osmolality, white cell count, protein, specific gravity, and such conditions as multiple myeloma and haematuria, may be detected by testing urine from a patient using appropriate known sensors in combination with the disclosed sensors.

In one example system, the processing means may be configured to receive incontinence pad type information for an absorbent article worn by a subject and, based on the pad type indicator and the continence-related data, calculate a risk of wetness leakage from the absorbent article. A sensor status circuit may be combined with identifier circuitry, or it may be provided separately, to integrate information to identify the patient and/or the type of incontinence article being monitored. Information on the patient or type of absorbent article may be obtained through automated sensing or manual entry.

The system may include separate input means to facilitate manual entry of non-wetness event data, including one or more actuators on the transmitter; optically, electronically, or otherwise scanning a code from a card or other reference guide, or manual entry of a code; wherein any of the foregoing are optionally performed using a hand held device. Additional means may be included to sense movement of the subject. The reader or transmitter may be combined with sensing means to determine changes in the position of the subject, including e.g. a position tracking device (such as GPS) and/or one or more motion detectors such as an accelerometer or pressure transducer providing an indication of movement of the subject. Such detectors may be configured to detect wandering or falls that are communicated to the processor in real time for notification to a caregiver.

Potential readers include both hand-held and fixed readers, including readers that are bed-mounted, chair mounted (including e.g. wheel-chair mounted or rocking chair mounted), cart-mounted, wall-mounted, furniture mounted, or mounted on or in any other mobile or stationary support unit for a patient, where such readers may be battery-powered or powered by a wired connection to a wall socket, for example.

Processing means may be provided in a single processing device or may be provided by a number of discrete or connected processing units or processing elements in which each may perform different processing functions that contribute to the overall functionality of the system. As such, various functions of the processing means may be provided by various elements of the system including a processing element which may, in some embodiments, be associated with continence sensors per se, and/or a processing element contained within transmitters or receivers of the system, or a processing element provided as part of a "central monitor" in a particular site employing the system, or in communication with one of more of the foregoing by wired or wireless connection with other processing elements through wide area networks (WANs), local area networks (LANs), the Internet, and other networks as may be known in the art, including, for example, by proprietary RF link, wired Ethernet, wireless

WO 2013/022742

PCT/US2012/049488

Ethernet, Zigbee, Bluetooth, etc. The database may be hosted locally at the customer site, remotely at a separate facility, or in the cloud. User interfaces are typically provided for report generation and statistical inquiries.

The processing means may be configured to cause an alert or otherwise provide feedback to the caregiver on the status of the sensor(s) so that the caregiver can attend to the subject being monitored. Alternately, or in addition, the processing means may be configured to automatically correlate patterns in continence-related data and non-wetness event data. The processing means may be configurable to receive inputs from multiple types of sensors. This may be achieved, for example, by collecting continence data from a sensor associated with an absorbent article worn by a subject; collecting non-wetness event data pertaining to the subject; and using the collected non-wetness event data and sensor data to optimize a mathematical model for monitoring incontinence in a subject, and using the optimized model to monitor incontinence in a subject wearing an absorbent article with a sensor of the current invention. In some embodiments, the processing means receive multi-site continence-related data obtained from a plurality of sites where the system is used to monitor subjects for incontinence. The processing means may include a data compiling processor receiving the multi-site continence-related data. The system may provide a data store for storing the multi-site data, and one or more network communication elements connecting the one or more sites with the data compiling processor. The processing means may utilize data obtained from the plurality of sites to perform analysis including: identifying trends in usage of absorbent articles; evaluating care assessments for subjects being monitored; identifying trends in caregiver behavior; identifying correlations between continence-related data, event data, and other conditions applicable to the group of patients; benchmarking performance of different incontinence products or different models of continence care, and so forth.

One example of a wetness detection system may include a wetness sensor installed into a brief, a bed-mounted reader including appropriate electronics and an antenna that is capable of coupling to the sensor, a wireless network connection, and a database for storage and analysis of data. The bed-based reader may include a resonance detection circuit and a tuned antenna installed in the bed, and may include a presence-sensing unit, such as a pressure sensor, to determine if the patient is in the bed. The wireless network connection can be a proprietary RF link, and the database may be stored on a machine that can be accessed by the care facility's network. Along with the database, the machine can run algorithms to conditionally monitor the data. One algorithm may report when patients become wet and automatically notify the health care staff. The system may collect information about each patient who is wearing a brief with the wetness sensor coupled to a bed-based reader, and may remotely log it in the database. With this type of continuous monitoring, compliance with existing standard F-TAG 315 is demonstrated since the minimum check-time of once every two hours is exceeded. The system may also automatically log when the brief is changed, as well as when the patient is in or out of bed. This information can be used to generate a typical routine for each patient. By utilizing this system and the automatic documentation and trend analysis, a more accurate predictive toileting schedule can be created. This may be more effective

than attempting to train and schedule toilet activities around other activities such as eating or sleeping schedules.

There are several potential advantages and uses for such systems. The system may be used for training staff to perform duties, including: selecting a suitable absorbent article or pad type; using the system to monitor and/or assess incontinence sufferers; timely attendance to subjects with incontinence; evaluating a condition of a subject suffering incontinence; developing a continence care plan for a subject; and evaluating the effectiveness of a continence care plan. Day-to-day trends can be monitored, including required brief changes, average number of briefs used, time spent out of bed, average time wet before changed, and more, to develop predictive toileting schedules. Deviations from the trends can also be monitored. The processing means may be configured to correlate patterns in continence-related data and non-wetness data with one or more disease condition indicators and provide guidelines to investigate the presence of a disease state. Checking for anomalies could enable the prediction of health issues such as dehydration, UTIs, yeast infection, and so forth earlier than would be predicted without this system. This type of trend analysis can also help monitor the quality of care or help identify gaps in staffing. For instance, a high average time wet before change could indicate under-staffing at the health care facility. By monitoring the average number of briefs used, the average time wet before being changed, and the amount of insult in the brief, the system can predict which patients are at higher risk for developing skin/pressure ulcers. The system can encourage additional checking and faster response times for these patients to minimize the escalation of their condition. The system can also automatically generate paperwork that is required should a skin/pressure ulcer form. This automatically-generated documentation may ensure that the patient's condition is properly reported so that further deterioration is minimized, and may bring visibility to the problem so that it does not go unnoticed during staff shift changes.

Unless otherwise indicated, all numbers expressing feature sizes, amounts, physical properties, and so forth used in the specification and claims are to be understood as being modified by the term "about". Accordingly, unless indicated to the contrary, the numerical parameters set forth in the specification and claims are approximations that can vary depending on the desired properties sought to be obtained by those skilled in the art utilizing the teachings of the present application.

Spatially related terms, including but not limited to, "lower", "upper", "beneath", "below", "above", and "on top", if used herein, are utilized for ease of description to describe spatial relationships of an element(s) to another. Such spatially related terms encompass different orientations of the device in use or operation in addition to the particular orientations depicted in the figures and described herein. For example, if a cell depicted in a figure is turned over or flipped over, portions previously described as below or beneath other elements would then be above those other elements.

Various modifications and alterations of this invention will be apparent to those skilled in the art without departing from the scope and spirit of this invention, and it should be understood that this invention is not limited to the illustrative embodiments set forth herein.

1. A sensor, comprising:
 - a self-supporting substrate; and
 - 5 an electrically conductive trace carried by the substrate and patterned to provide at least a portion of a tuned RF circuit, the RF circuit being characterized by an impedance or resistance and being disposed on only one side of the substrate;
 - wherein the electrically conductive trace is not self-supporting; and
 - wherein the substrate is adapted to dissolve, swell, or otherwise degrade when contacted by a
 - 10 target fluid, such that the impedance or resistance of the RF circuit changes by at least a factor of 5.
2. The sensor of claim 1, wherein the substrate dissolves when contacted by the target fluid.
- 15 3. The sensor of claim 1, wherein the substrate swells when contacted by the target fluid.
4. The sensor of claim 1, wherein the substrate is or includes a flexible film having a smooth major surface.
- 20 5. The sensor of claim 1, wherein the substrate is or includes polyvinyl alcohol (PVA).
6. The sensor of claim 1, wherein the target fluid comprises a polar liquid.
7. The sensor of claim 1, wherein the target fluid comprises water.
- 25 8. The sensor of claim 7, wherein the target fluid is or includes one or more aqueous human body fluids.
9. The sensor of claim 1, wherein the electrically conductive trace comprises silver.
- 30 10. The sensor of claim 1, wherein the electrically conductive trace has a thickness of less than 1 micron.
11. The sensor of claim 10, wherein the electrically conductive trace has a thickness of less than 100 nanometers.
- 35 12. The sensor of claim 1, wherein the electrically conductive trace includes an induction coil.
13. The sensor of claim 1, wherein the electrically conductive trace is in intimate contact with the substrate.

14. The sensor of claim 1, wherein the electrically conductive trace has a variable thickness and/or variable width.

5 15. The sensor of claim 14, wherein the electrically conductive trace has a variable thickness, the thickness variation being associated with a structured interface between the conductive trace and the substrate.

10 16. The sensor of claim 1, wherein the tuned RF circuit further includes an electrically conductive linking member that connects two portions of the electrically conductive trace.

17. The sensor of claim 1, wherein the impedance or resistance of the RF circuit changes by at least a factor of 100 when the substrate is contacted by the target fluid.

15 18. The sensor of claim 17, wherein the impedance or resistance of the RF circuit changes by at least a factor of 1000 when the substrate is contacted by the target fluid.

19. The sensor of claim 1, wherein the electrically conductive trace substantially disintegrates so as to provide the RF circuit with an open circuit when the substrate is contacted by the target fluid.

20 20. The sensor of claim 1, wherein contact of the substrate by the target fluid substantially renders the RF circuit inoperative.

25 21. The sensor of claim 1, further comprising a skin-compatible adhesive disposed on an outer surface of the sensor.

22. The sensor of claim 21, wherein the adhesive comprises silicone.

30 23. An absorbent garment comprising the sensor of claim 1.

24. The absorbent garment of claim 23, wherein the absorbent garment includes a liquid-permeable sheet, a liquid-impermeable sheet, and an absorbent material trapped between the liquid-permeable sheet and the liquid-impermeable sheet, and wherein the sensor is disposed between the liquid-permeable sheet and the liquid-impermeable sheet.

35 25. A construction article comprising the sensor of claim 1.

WO 2013/022742**PCT/US2012/049488**

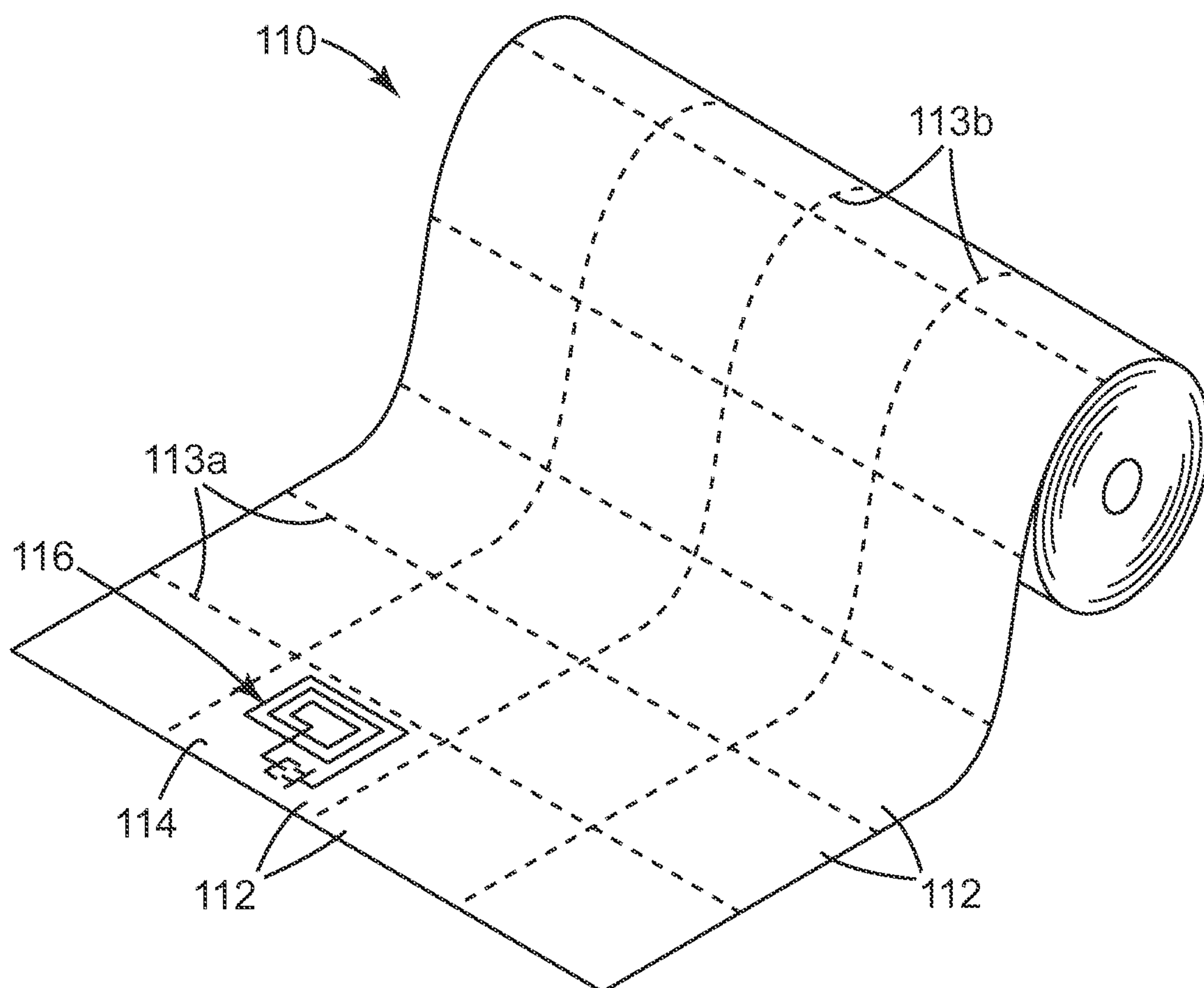
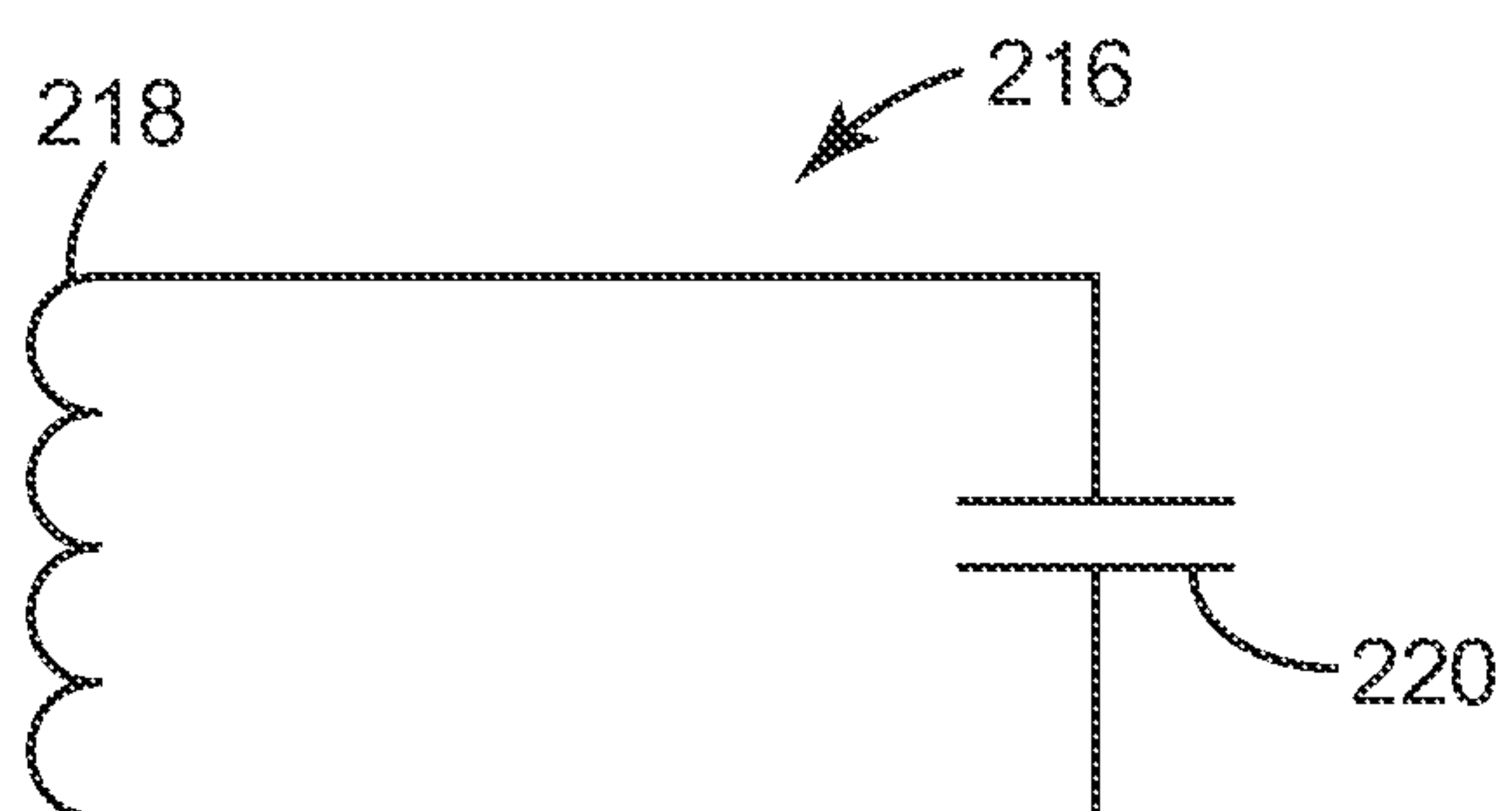
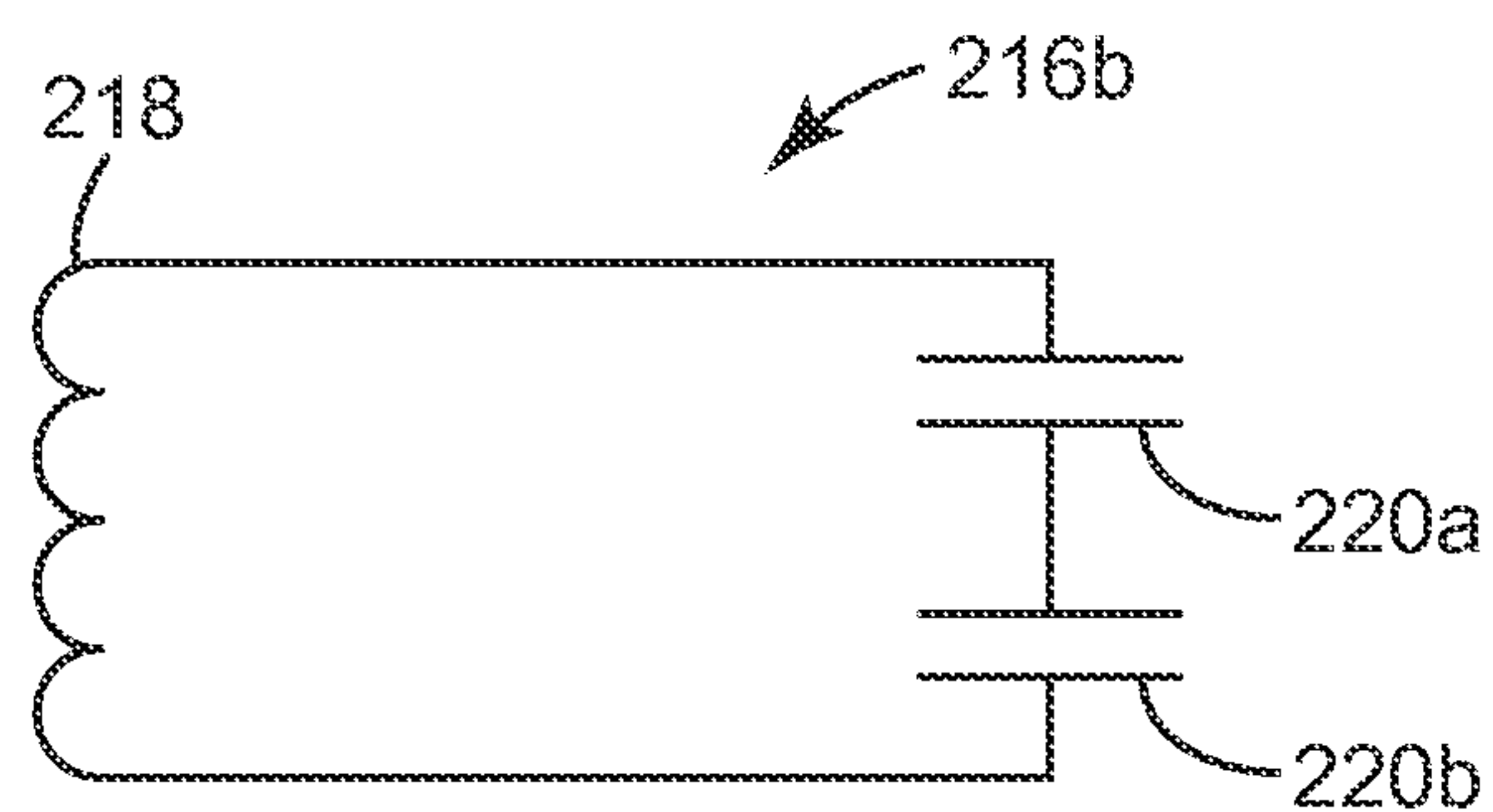
26. The article of claim 25, wherein the construction article is or includes wall board, insulation, flooring, roofing, and/or a fitting or support structure for a pipe.

27. A system, comprising:

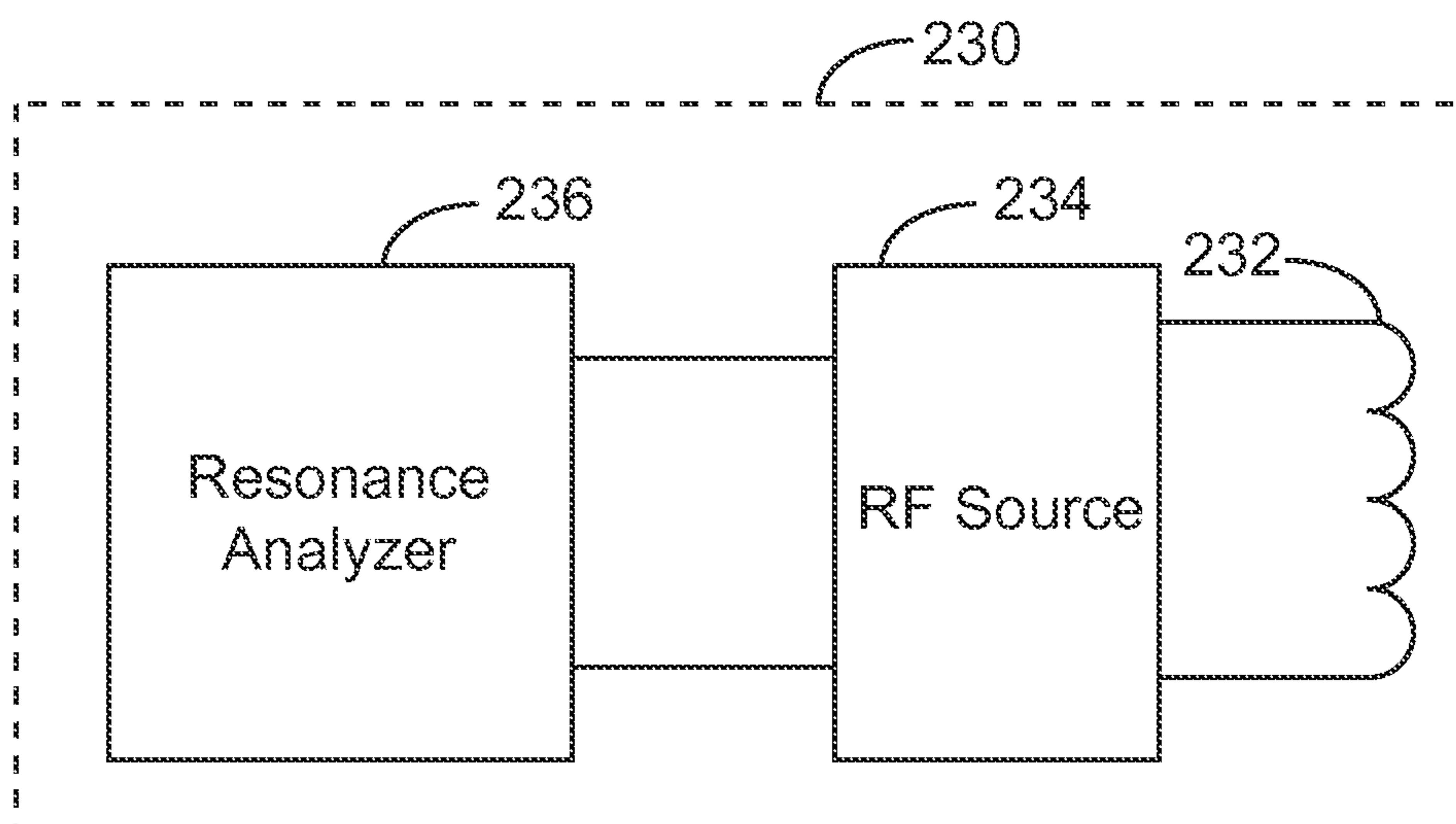
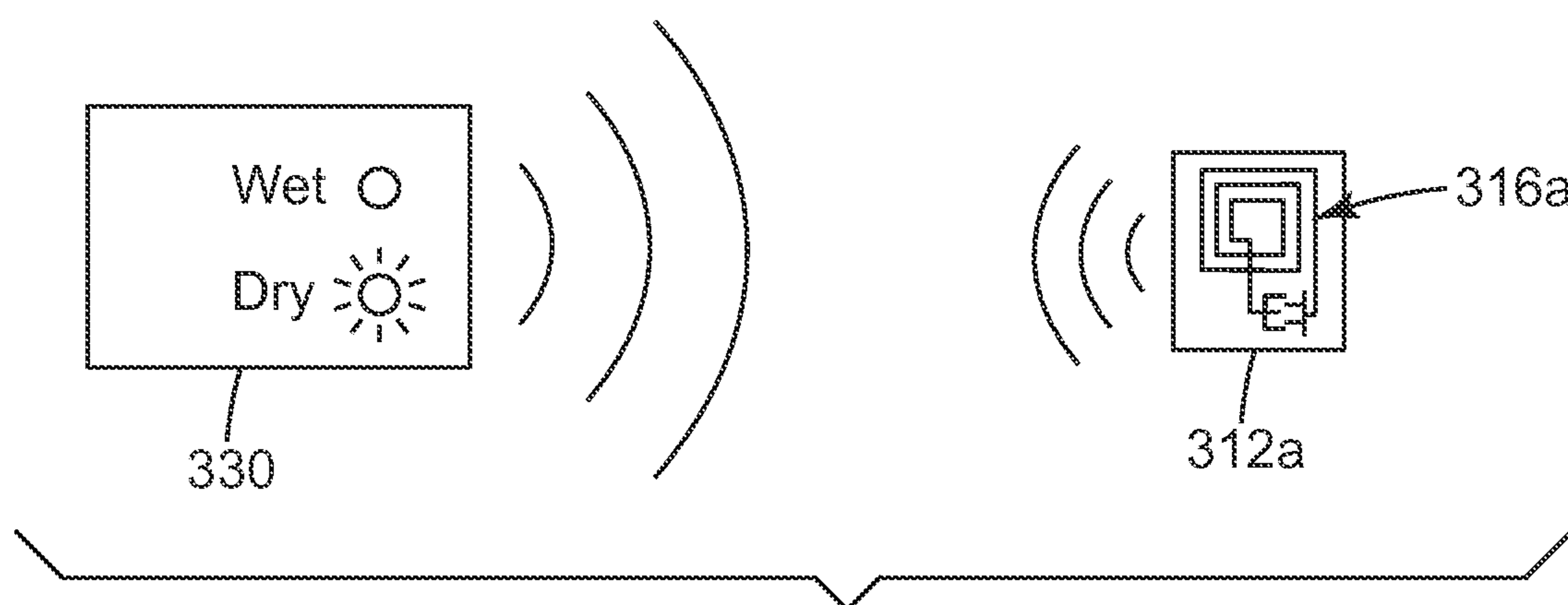
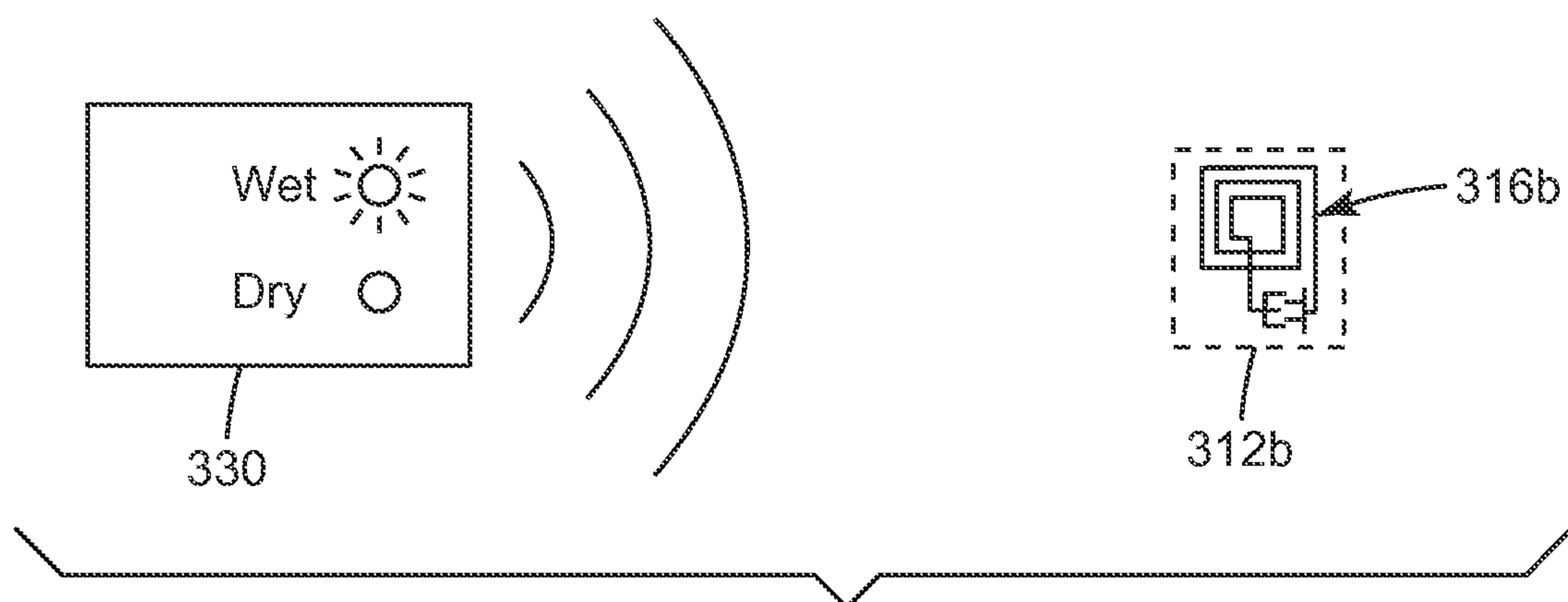
- 5 the sensor of claim 1; and
 a reader configured to remotely assess a condition of the tuned RF circuit.

28. The system of claim 27, wherein the reader is configured for mounting in or on a mobile or stationary support for a person.

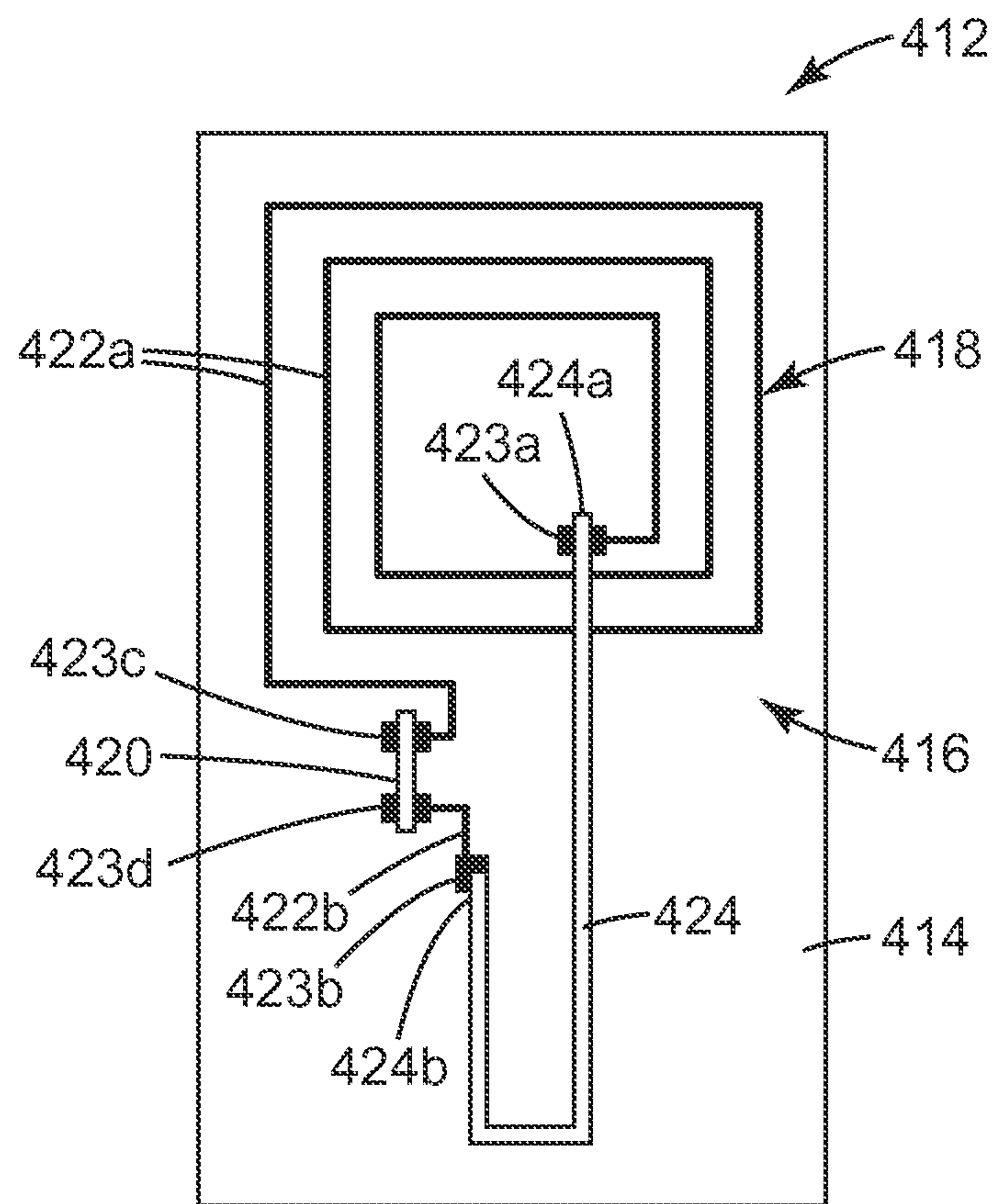
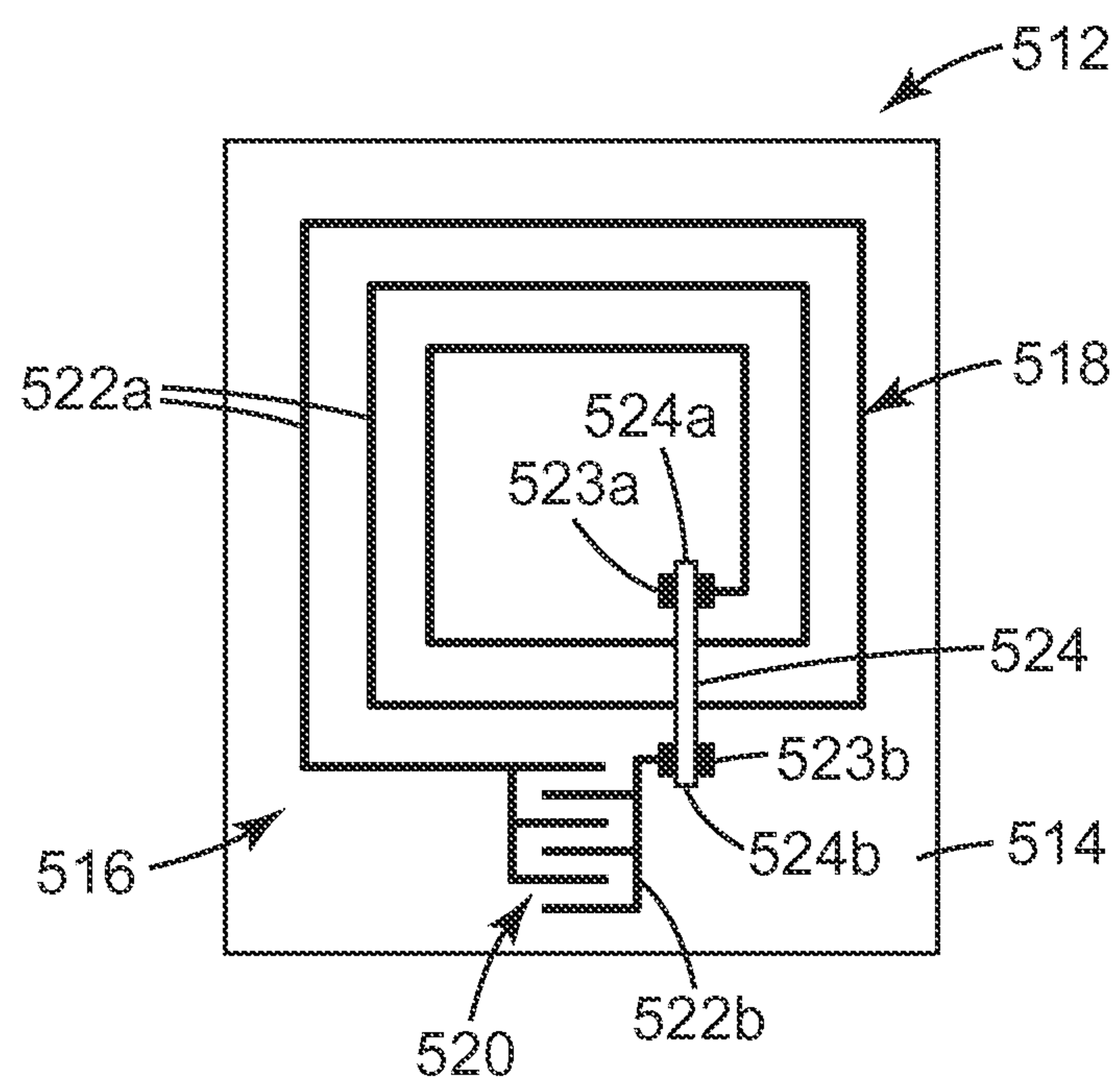
10

*Fig. 1**Fig. 2a**Fig. 2b*

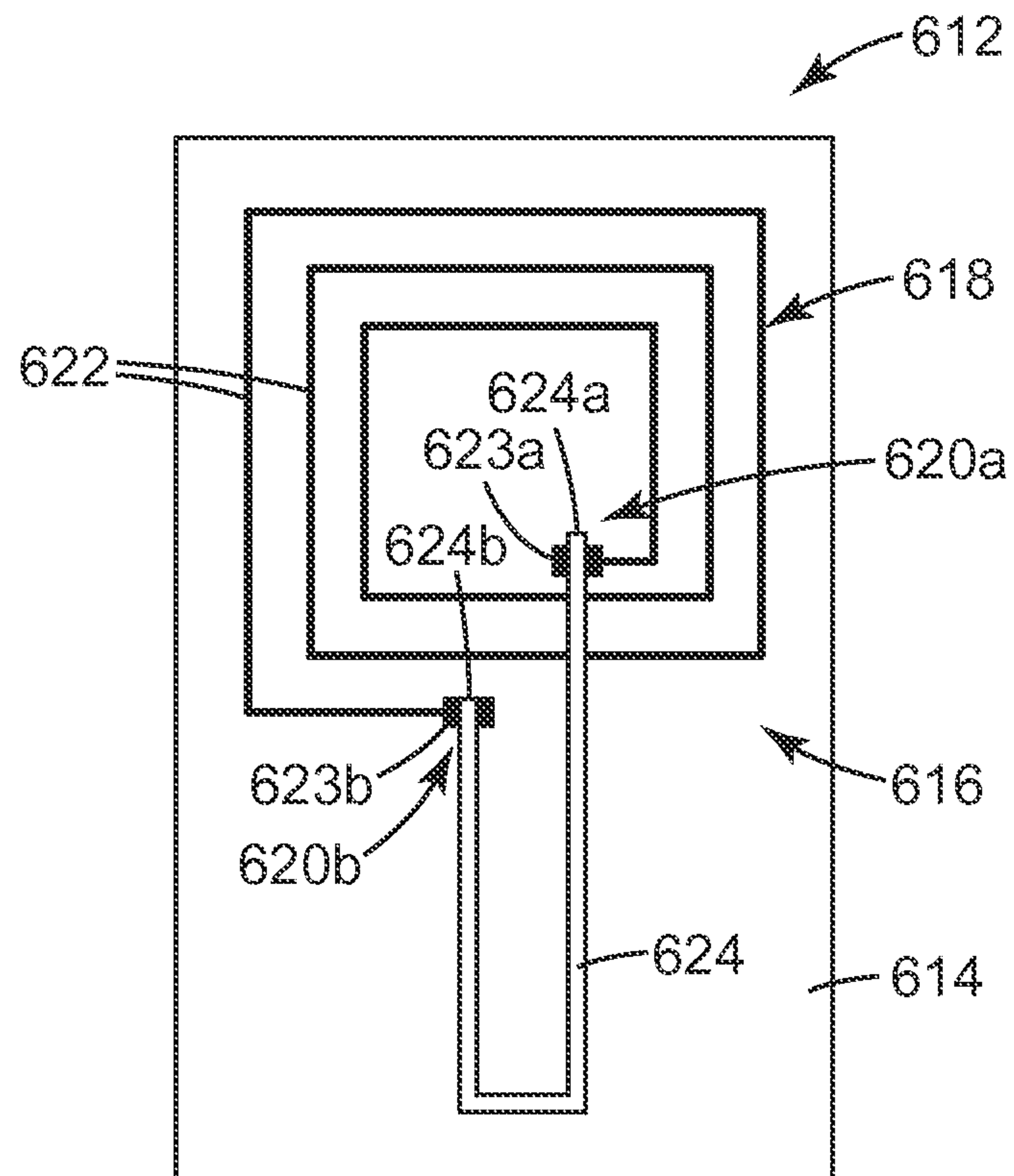
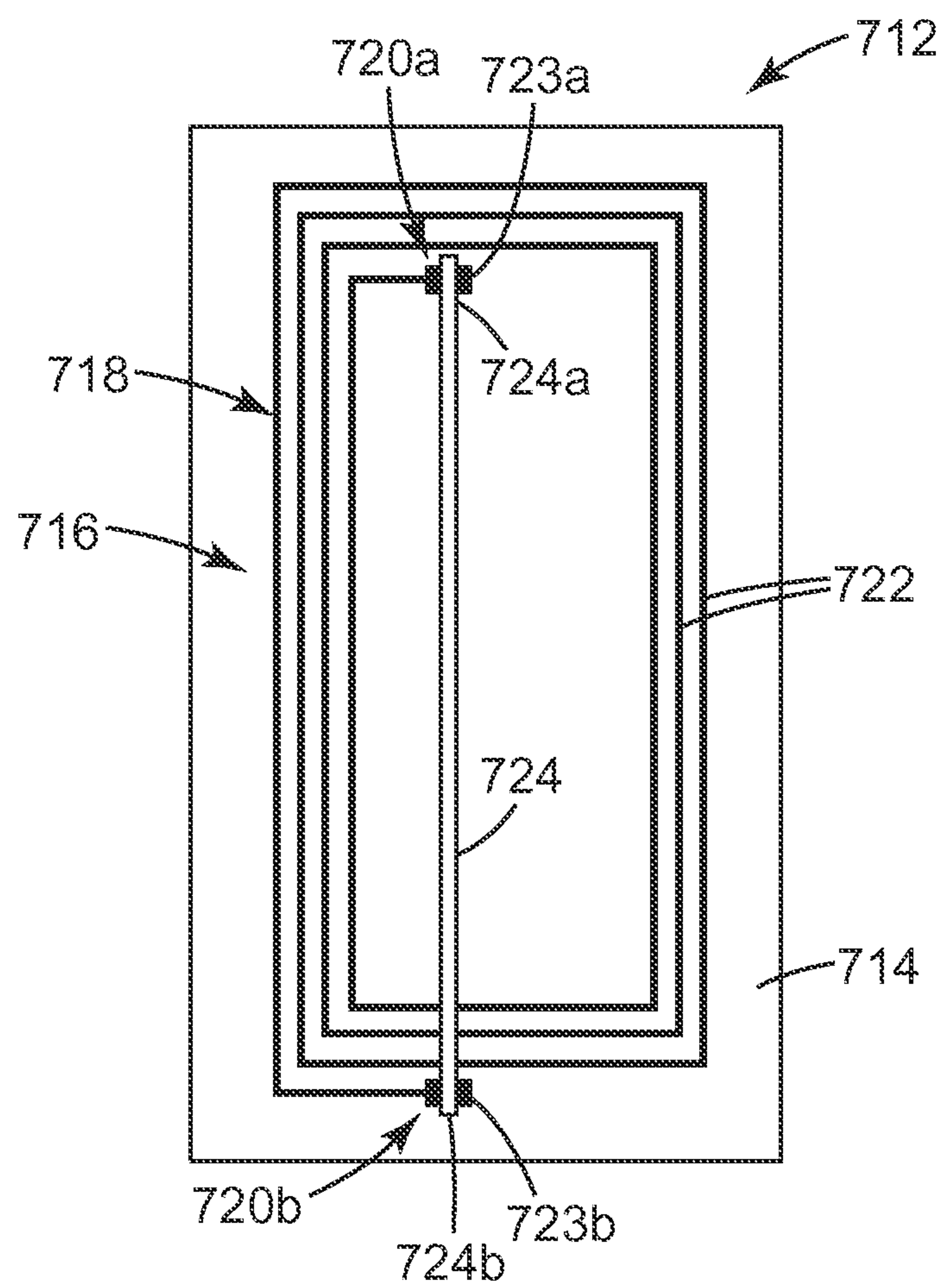
2/11

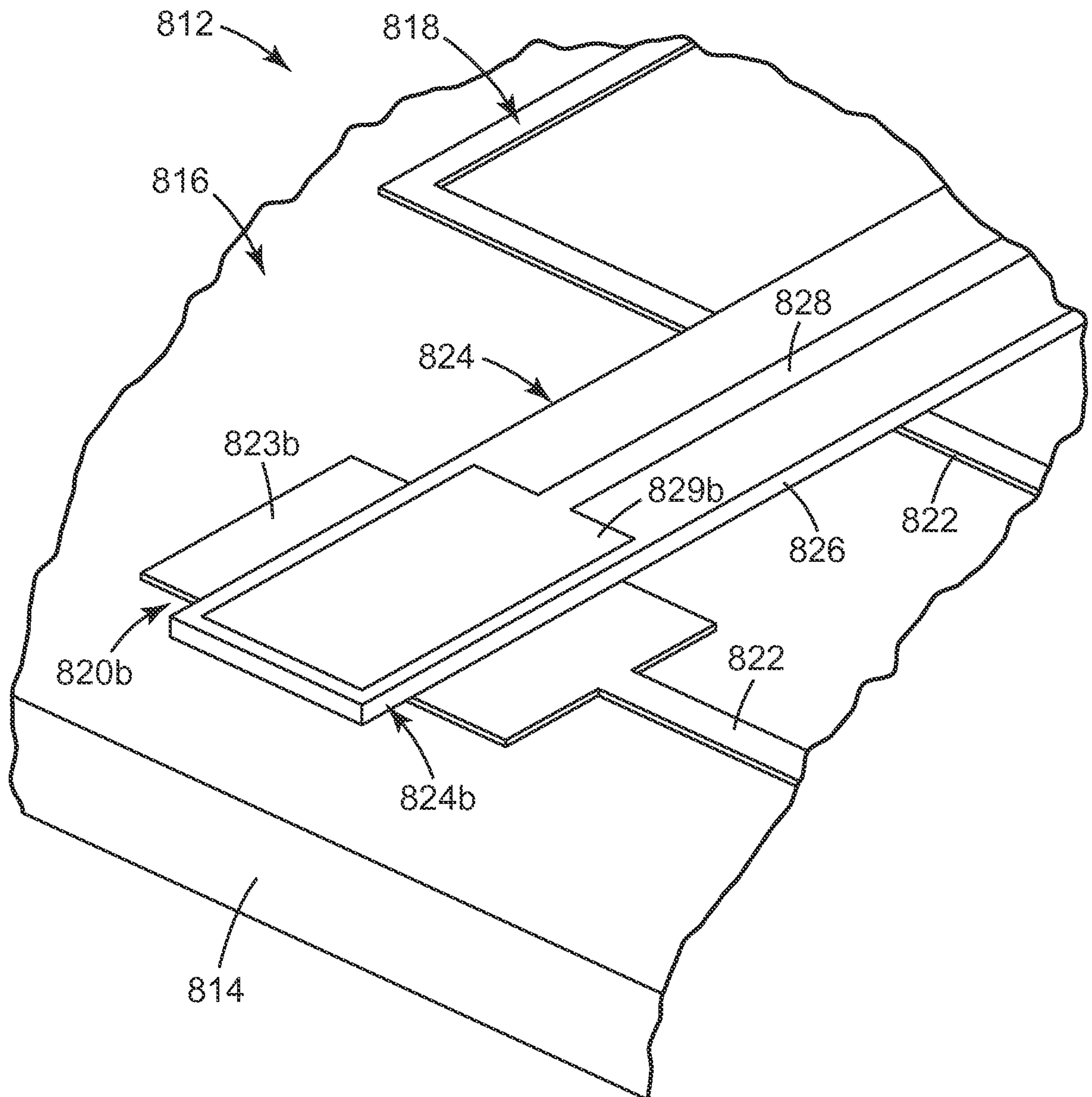
*Fig. 2c**Fig. 3a**Fig. 3b*

3/11

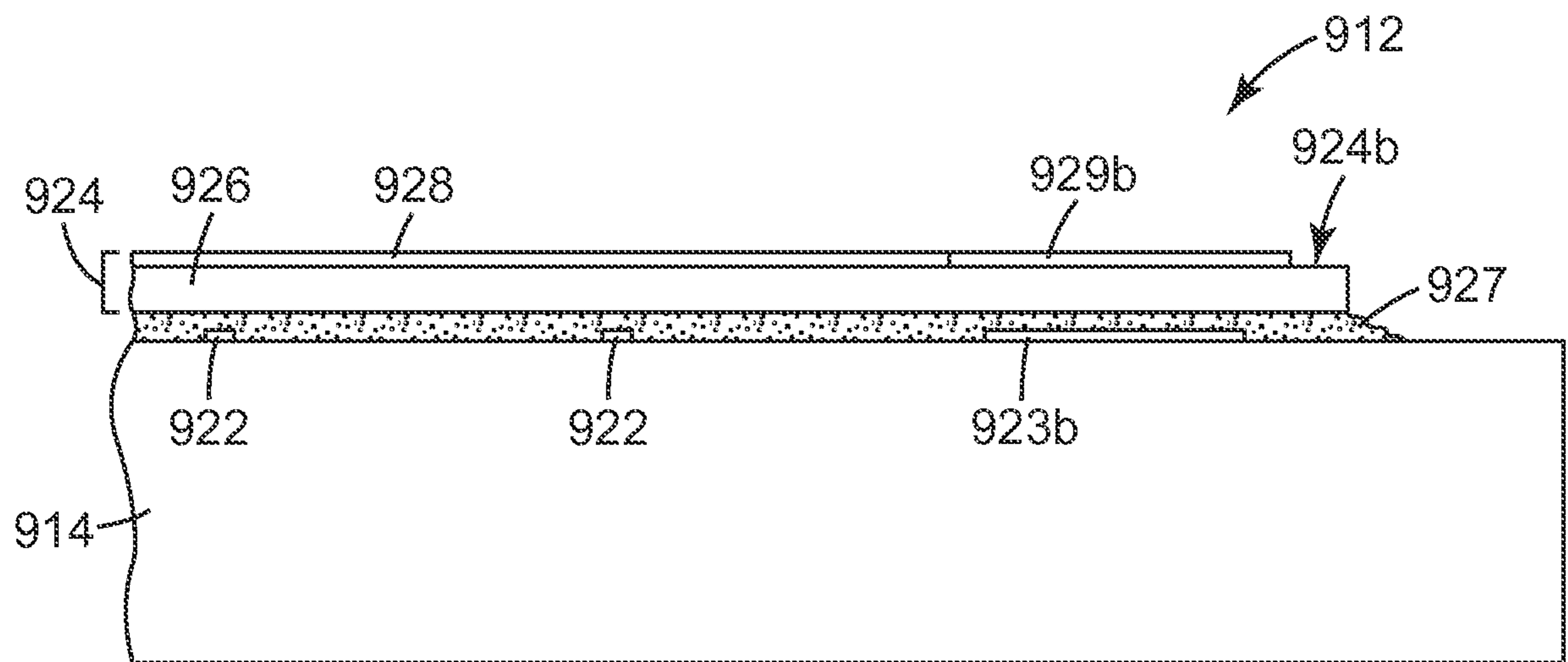
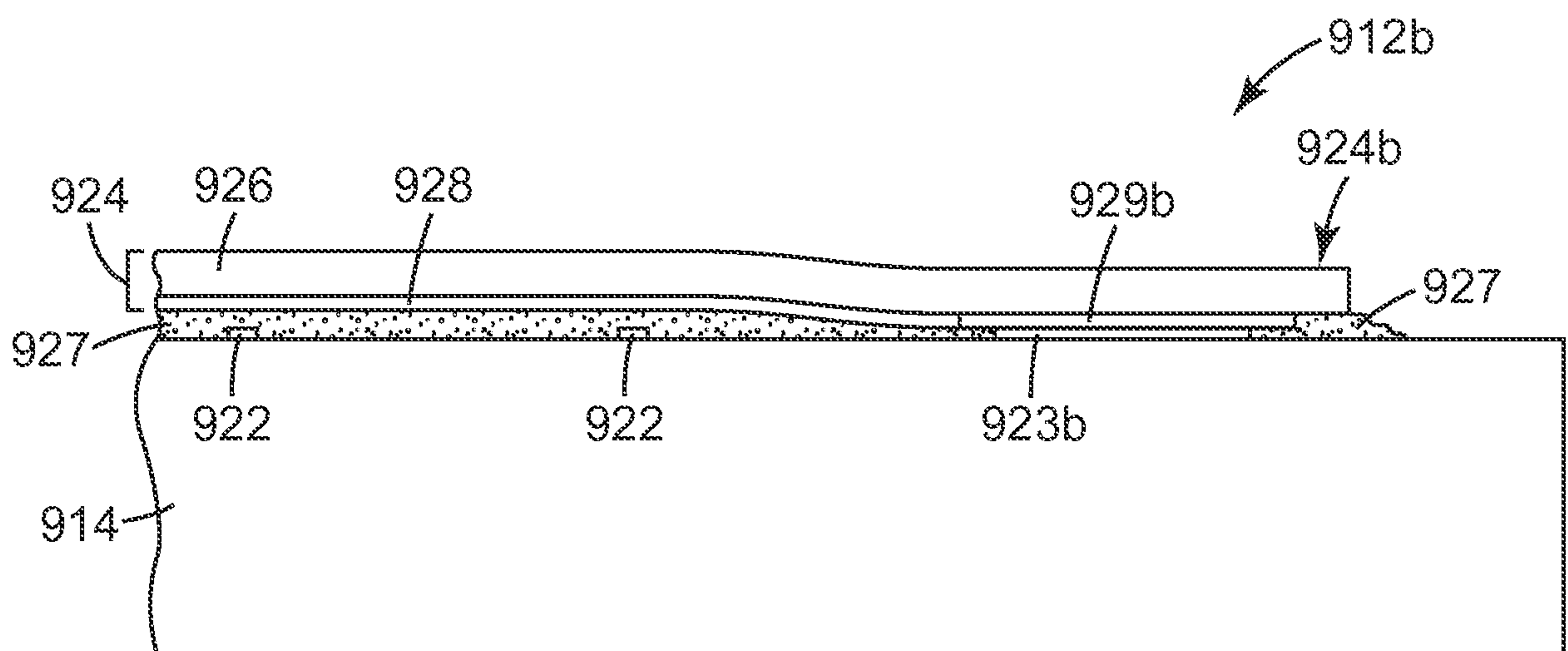
*Fig. 4**Fig. 5*

4/11

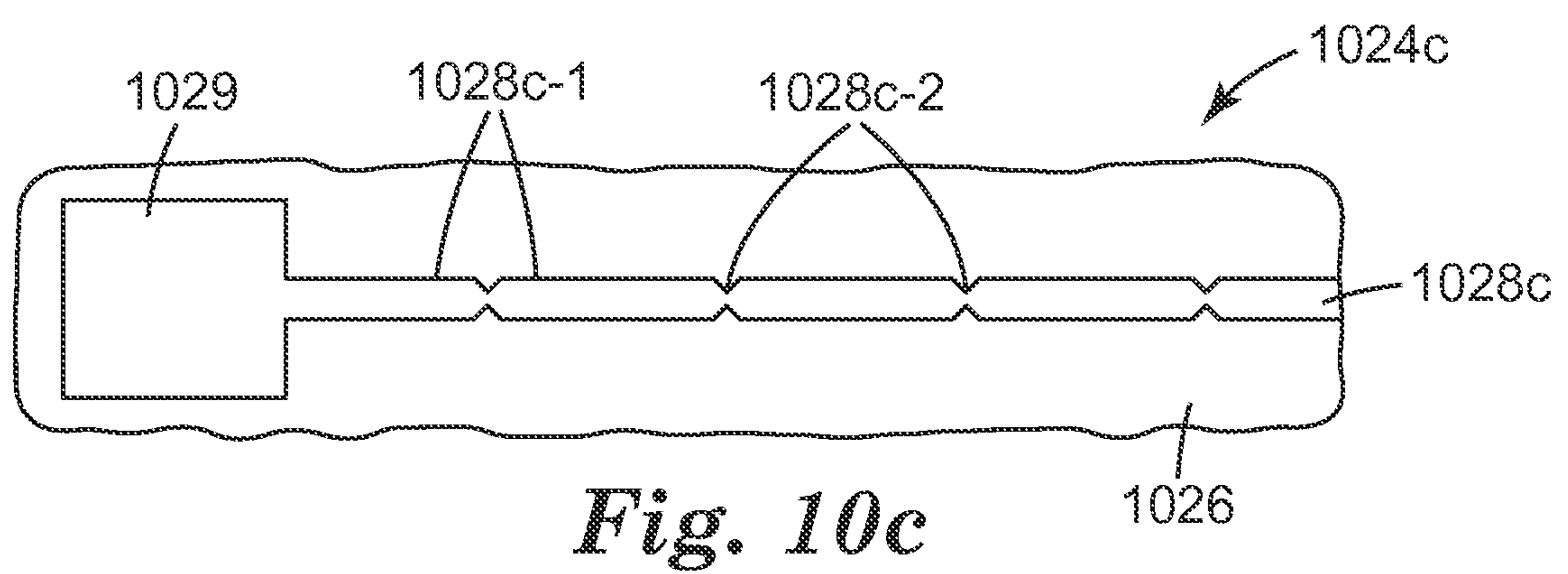
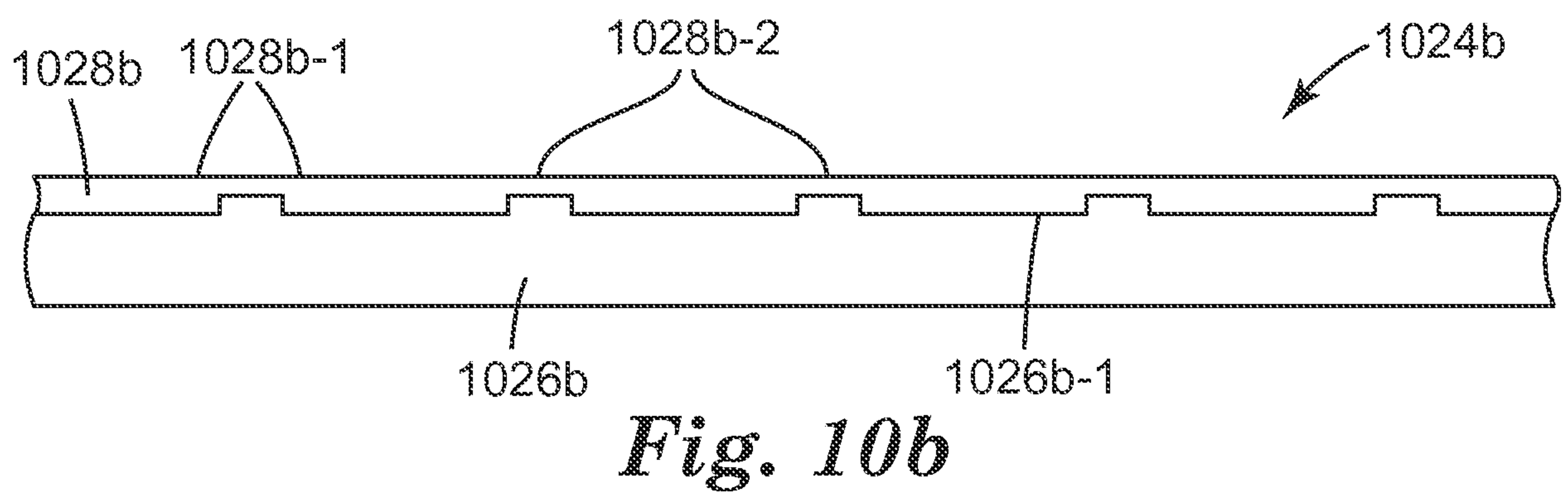
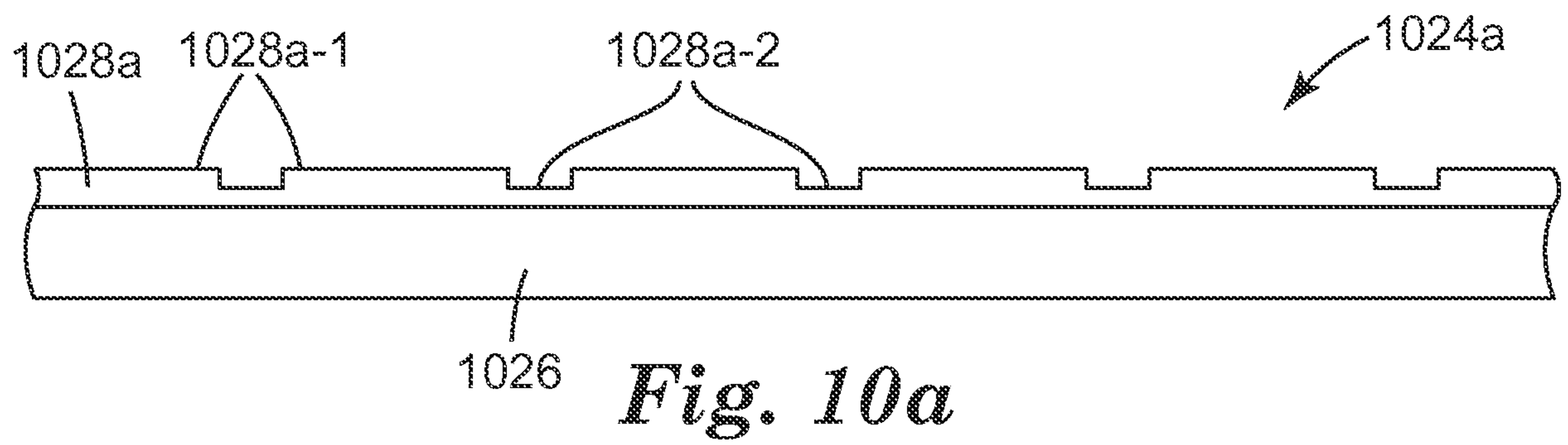
*Fig. 6**Fig. 7*

*Fig. 8*

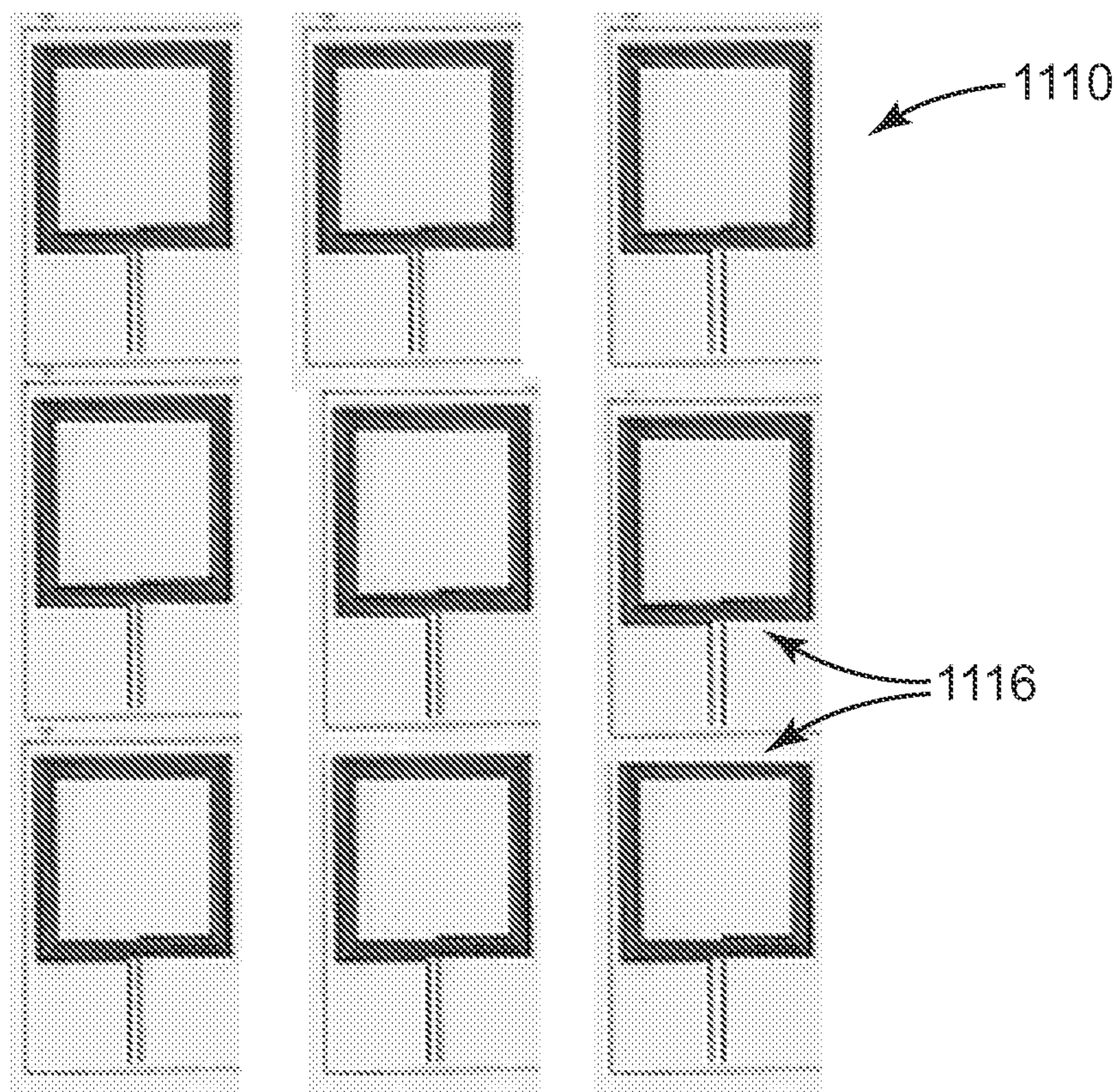
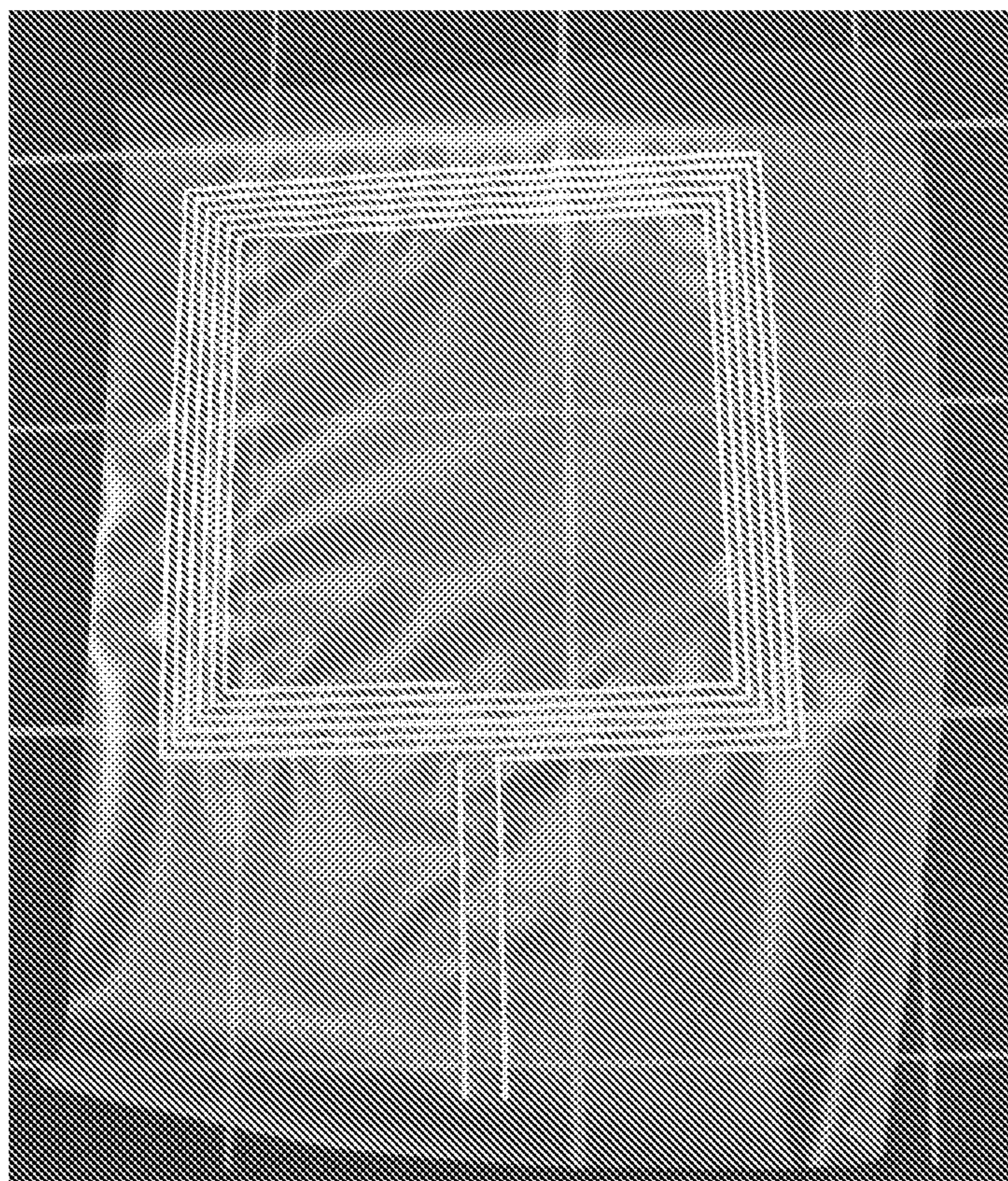
6/11

*Fig. 9a**Fig. 9b*

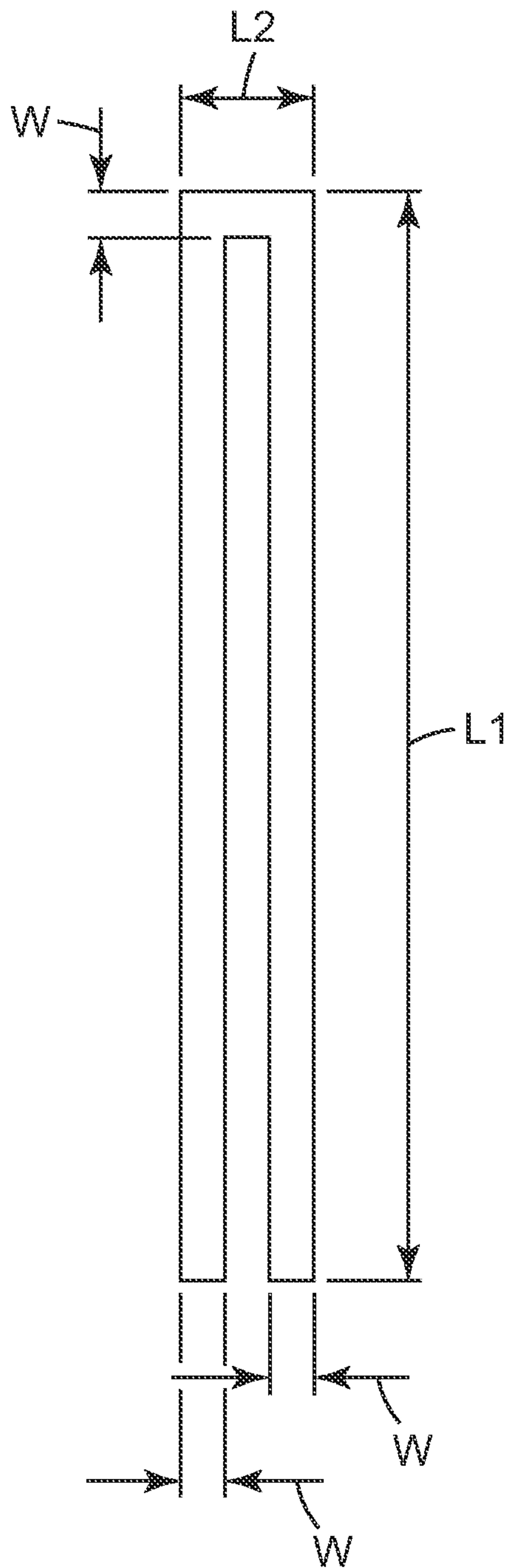
7/11



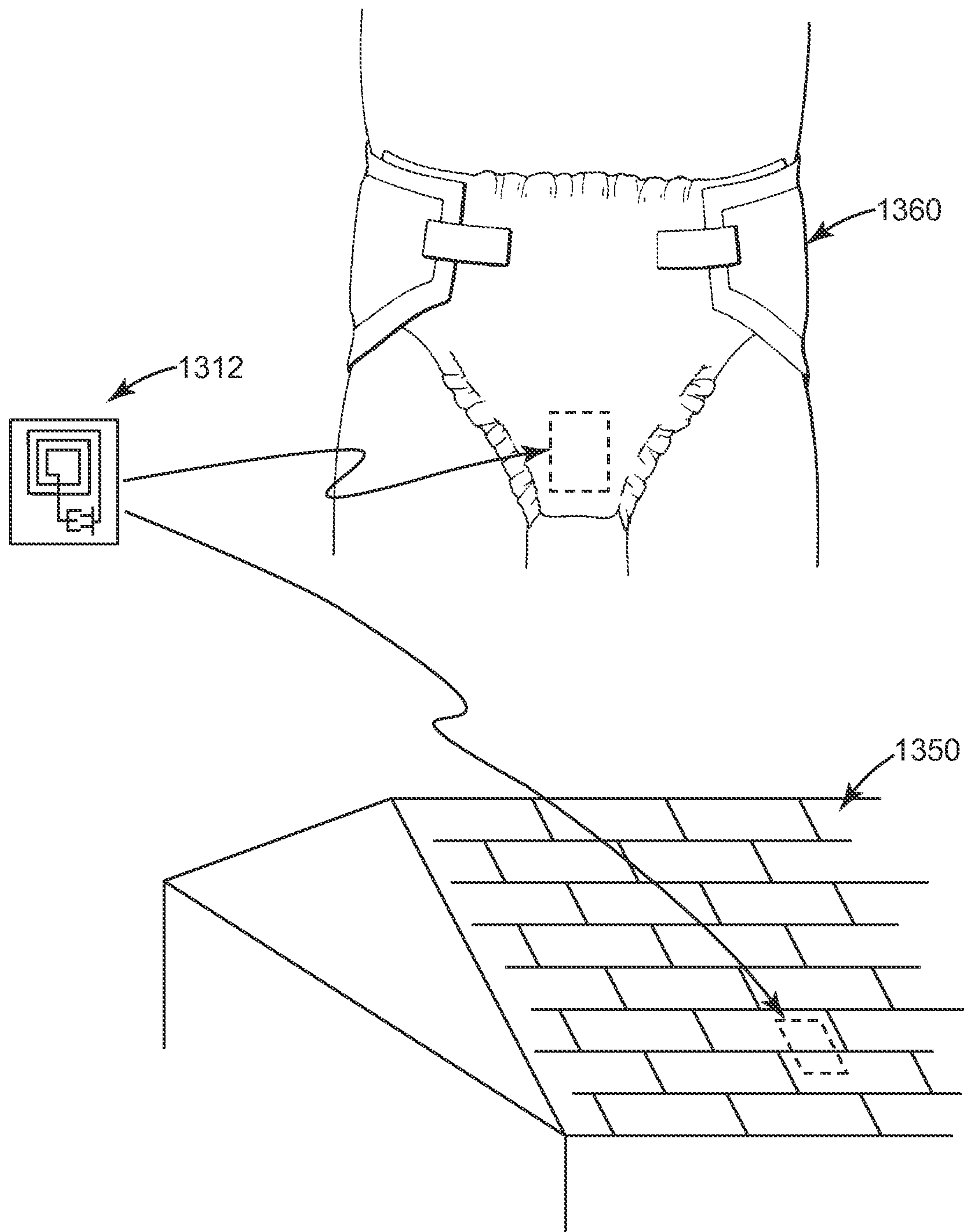
8/11

*Fig. 11**Fig. 12*

9/11

*Fig. 12a*

10/11

*Fig. 13*

11/11

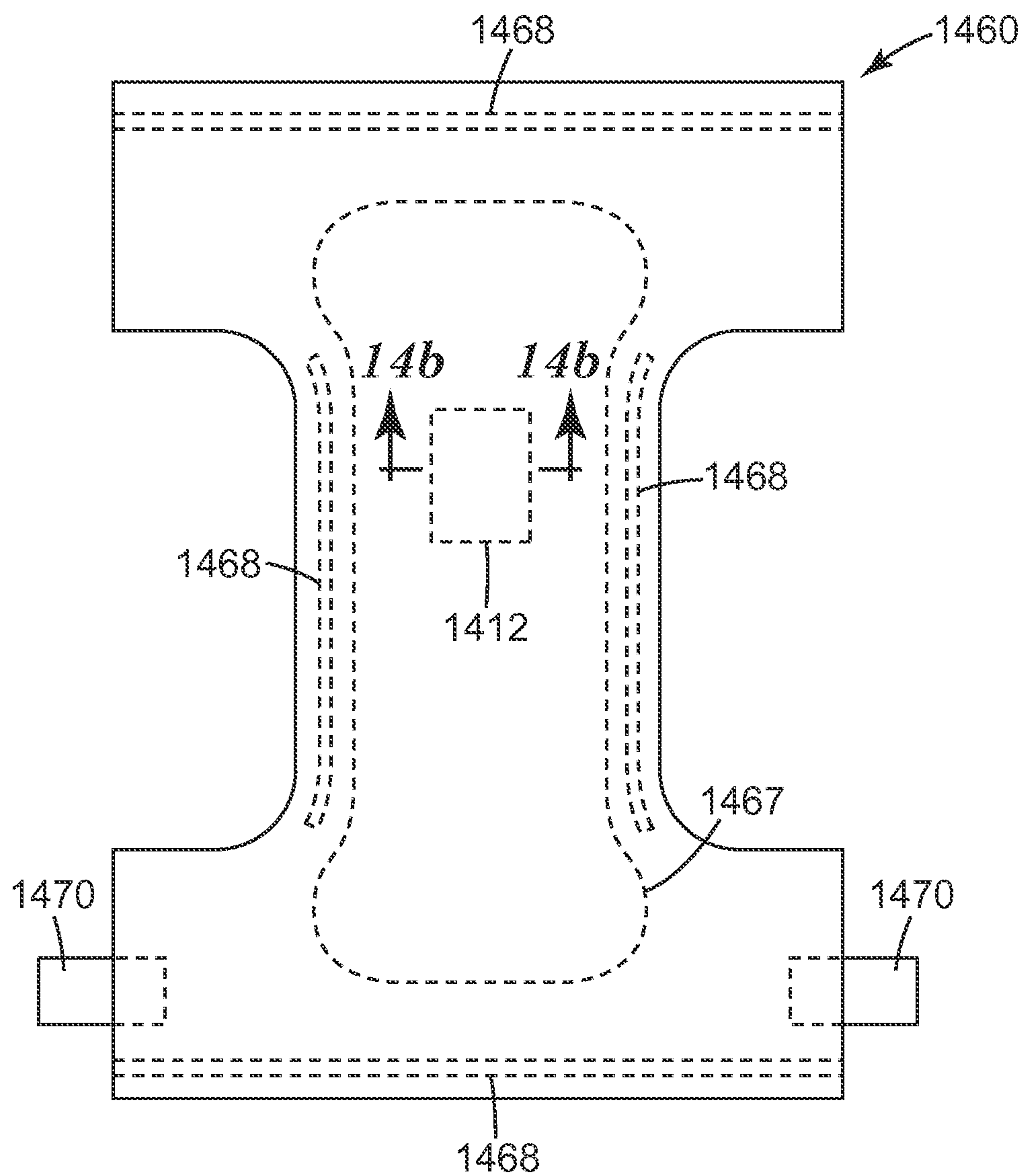
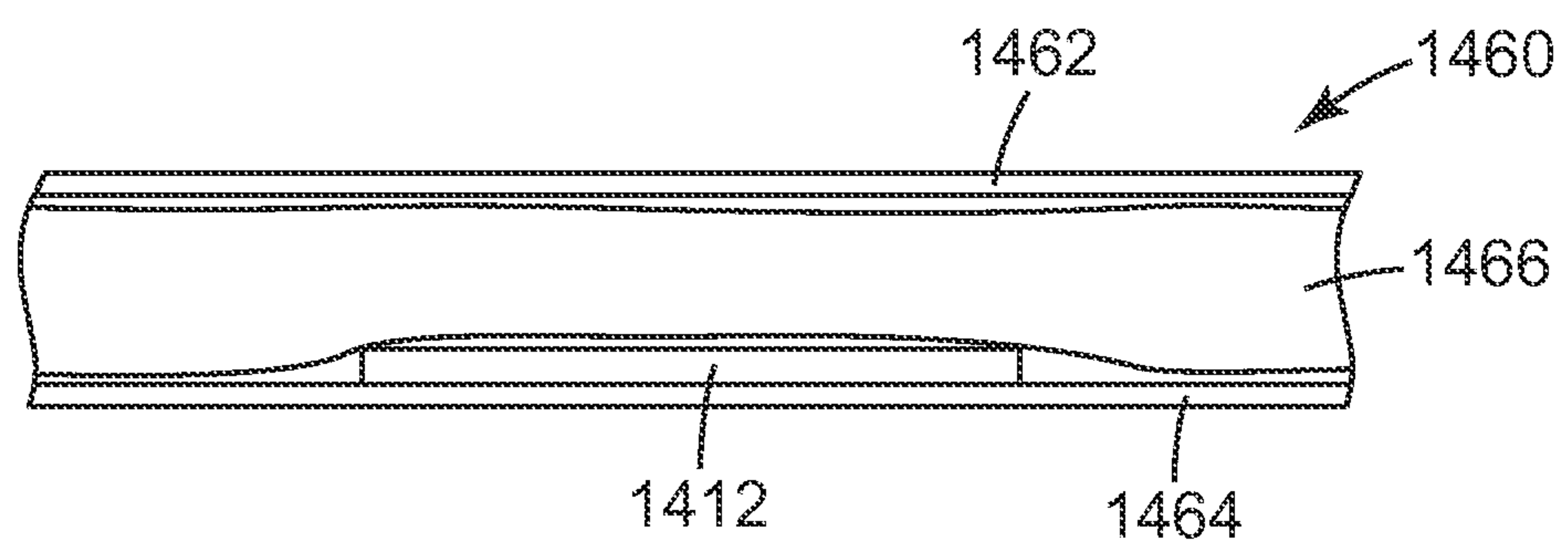
*Fig. 14a**Fig. 14b*



Fig. 4